

# EVM User's Guide: LP-AM263P

## AM263Px LaunchPad User Guide

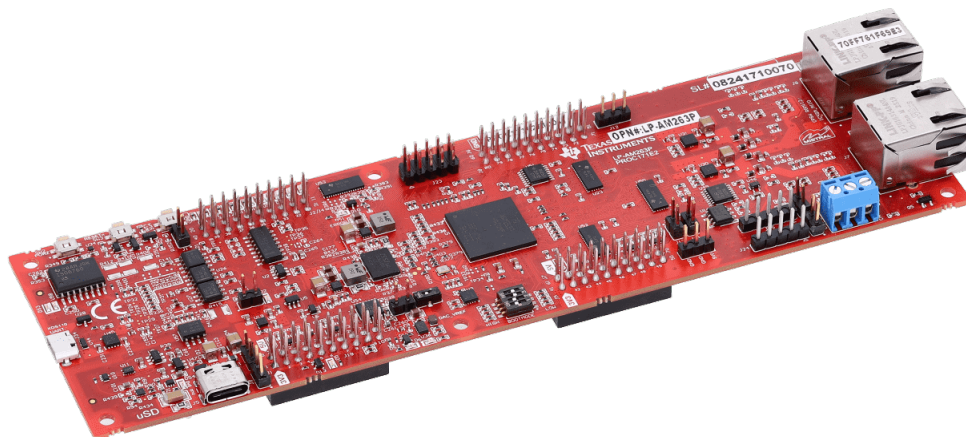


### Description

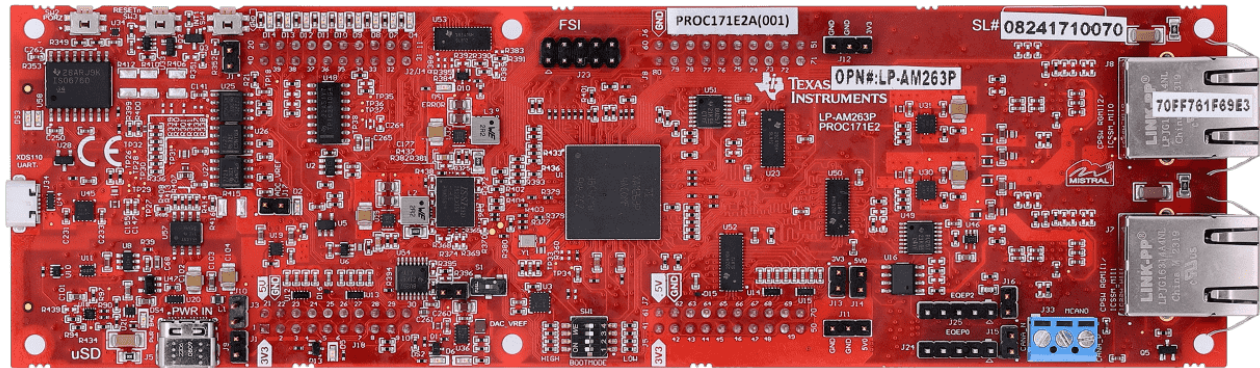
The AM263Px LaunchPad™ development kit is a simple and inexpensive hardware evaluation module (EVM) for the Texas Instruments™ Sitara™ AM263Px series of microcontrollers (MCUs). This EVM provides an easy way to start developing on the AM263Px MCUs with onboard emulation for programming and debugging as well as buttons and LEDs for a simple user interface. The LaunchPad also features two independent BoosterPack XL expansion connectors, onboard Controller Area Network (CAN) transceiver, two RJ45 Ethernet ports, and an onboard XDS110 debug probe.

### Features

- PCB dimensions: 195.56mm X 58.42mm
- Powered through 5V, 3A USB type-C input
- Two RJ45 Ethernet ports capable of 1Gbps speeds
- Onboard XDS110 debug probe
- Three push buttons:
  - PORz
  - User interrupt
  - RESETz
- LEDs for:
  - Power status
  - Power NOT Good
  - User testing
  - Ethernet connection
  - I2C driven array
- CAN connectivity with onboard CAN transceiver
- Dedicated FSI connector
- Discrete DC-DC buck regulators and LDOs that generate the required supplies with an additional option of Vpp LDO 1.7 (TLV75801PDRVR) as DNP
- TI Test Automation Header
- TIVA Test Automation Header
- MMC interface to micro SD card connector. Also a footprint option for users to mount Embedded Multi-Media Card (eMMC), like MTFC8GAMALBH-AT. Currently the eMMC is made DNP.
- Two independent Enhanced Quadrature Encoder Pulse (EQEP) based encoder connectors
- Two independent BoosterPack XL (40 pin) standard connectors featuring stackable headers to maximize expansion through the BoosterPack ecosystem
- Onboard memory:
  - 256 Mb OSPI Flash - ISSI IS25LX256-JHLE
  - 1 Mb I2C Board ID EEPROM



# 1 LaunchPad Module Overview



**Figure 1-1. AM263Px LaunchPad Board**

## 1.1 Introduction

This user's guide details the design of the EVM and how to properly use each interface. The user's guide also details many important aspects of the board including but not limited to power requirements, boot mode selections, and mux/switch signal routing.

## 1.2 Kit Contents

The Sitara AM263Px Series LaunchPad Development Kit contains the following items:

- AM263Px Sitara Series LaunchPad development board
- USB micro-B cable
- Micro SD card
- CAT5 Ethernet cable

---

### Note

The maximum length for any IO cables are required to be less than 3 meters.

---

The kit does not include:

- USB type-C 5V/3A AC/DC supply
- USB type-C cable

## 1.3 Device Information

### 1.3.1 System Architecture Overview

Figure 1-2 shows the overall top level architecture of the AM263Px LaunchPad.

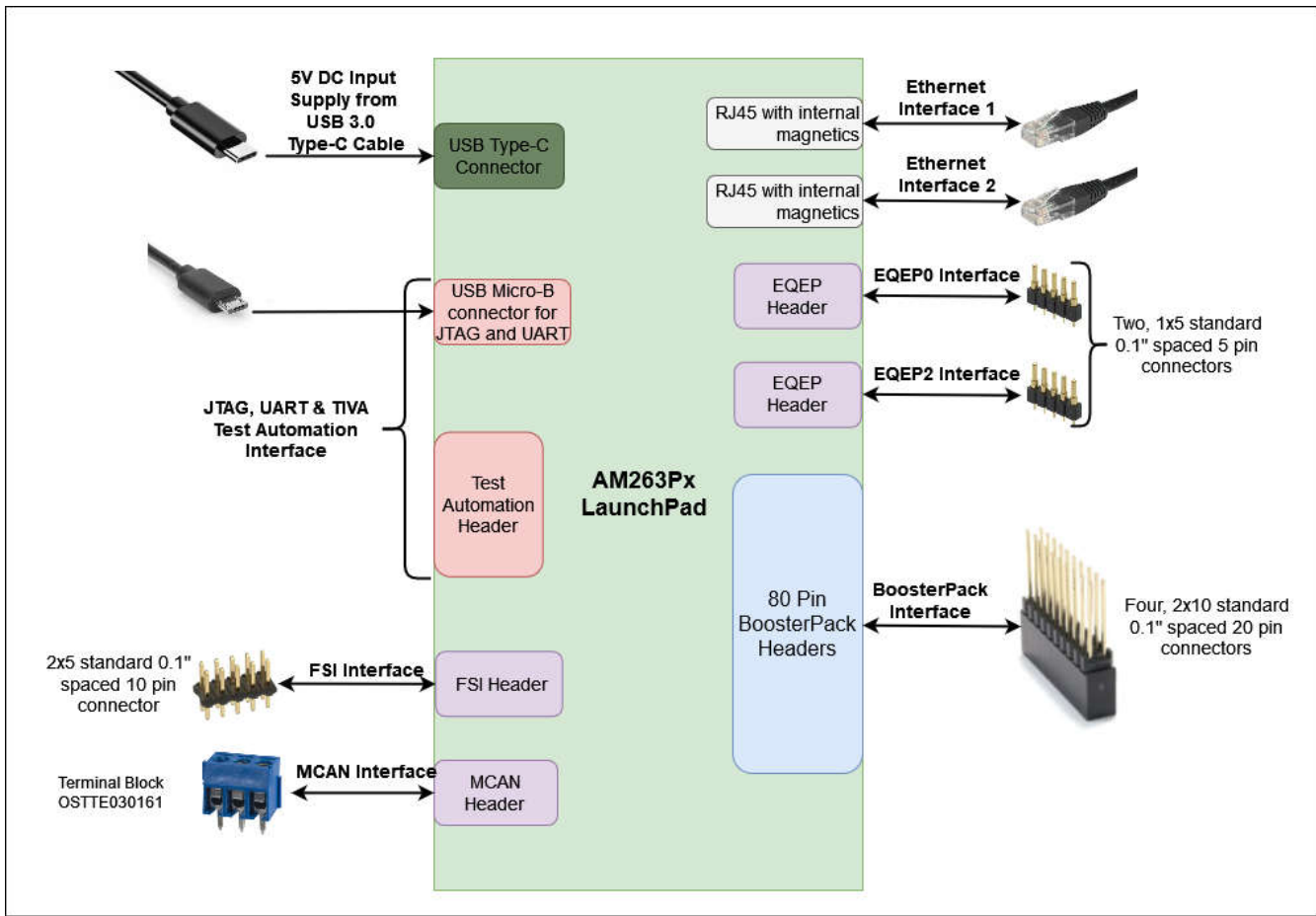


Figure 1-2. System Architecture

### 1.3.2 Security

The AM263Px LaunchPad features a High Security, Field Securable (HS-FS) device. An HS-FS device has the ability to use a one time programming to convert the device from HS-FS to High Security, Security Enforced (HS-SE) device.

The AM263Px device leaves the TI factory in an HS-FS state where customer keys are not programmed and has the following attributes:

- Does not enforce the secure boot process
- M4 JTAG port is closed
- R5 JTAG port is open
- Security Subsystem firewalls are closed
- SoC Firewalls are open
- ROM Boot expects a TI signed binary (encryption is optional)
- TIFS-MCU binary is signed by the TI private key

The One Time Programmable (OTP) keywriter converts the secure device from HS-FS to HS-SE. The OTP keywriter programs customer keys into the device efuses to enforce secure boot and establish a root of trust. The secure boot requires an image to be encrypted (optional) and signed using customer keys, which will be verified by the SoC. A secure device in the HS-SE state has the following attributes:

- M4, R5 JTAG ports are both closed
- Security Subsystems and SoC Firewalls are both closed
- TIFS-MCU and SBL need to be signed with active customer key

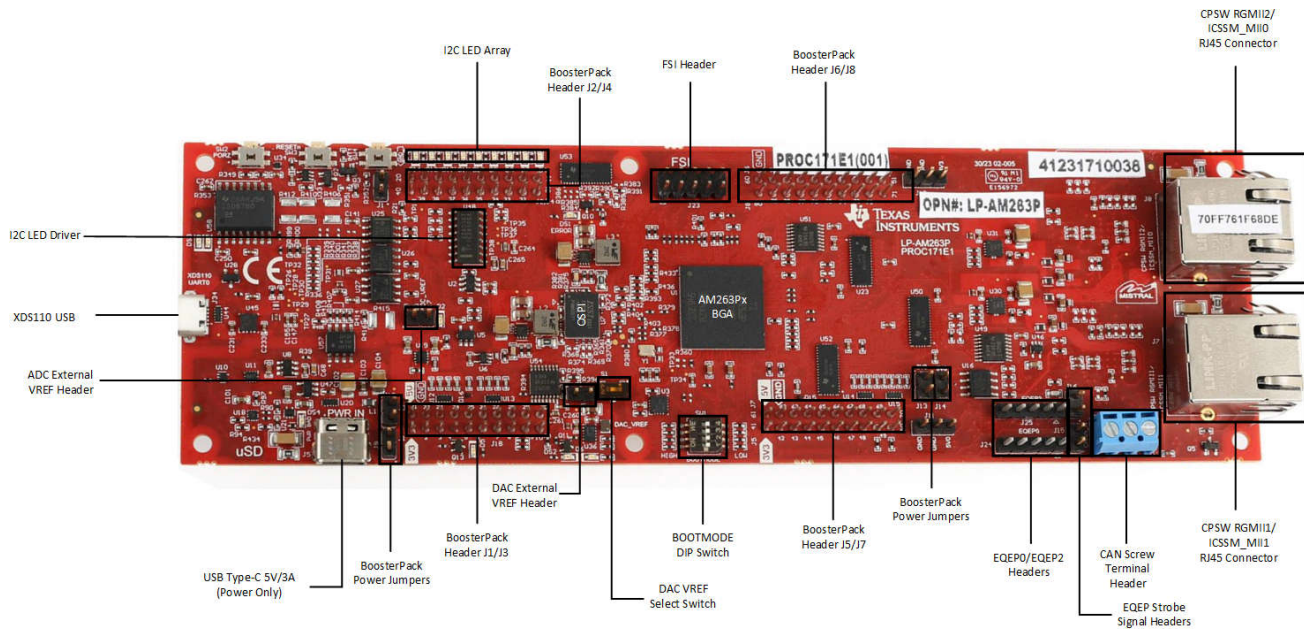


### 1.3.3 BoosterPacks

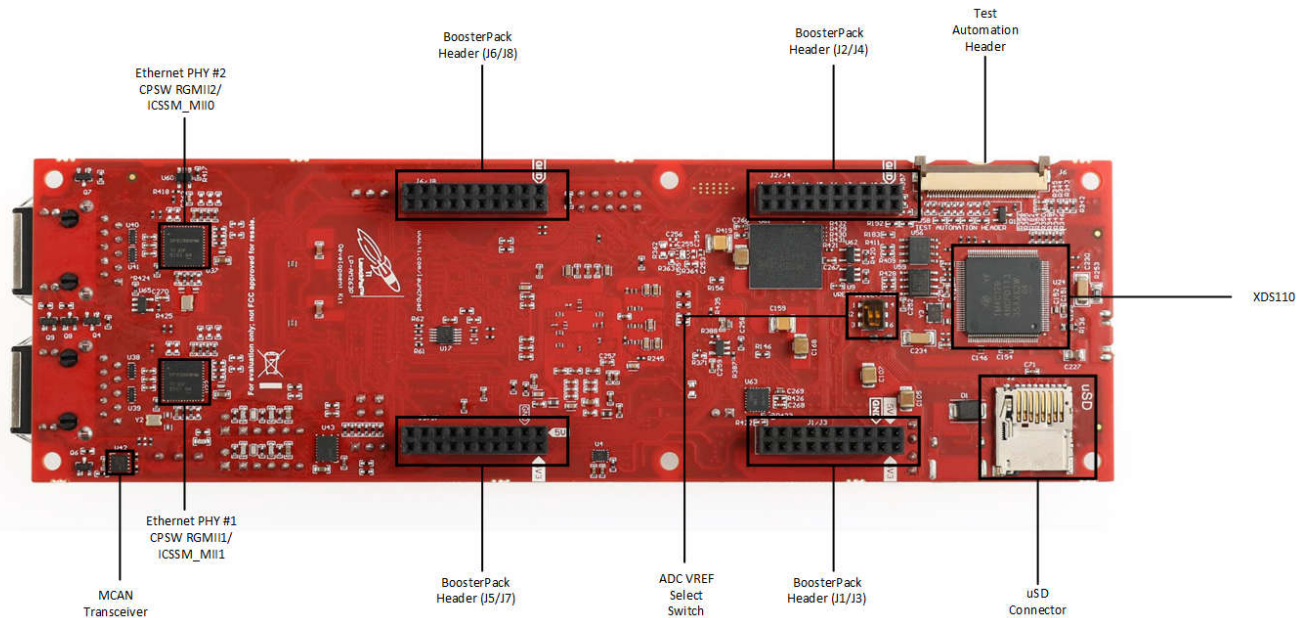
The AM263Px LaunchPad development kit provides an easy and inexpensive way to develop applications with the AM263Px Series microcontroller. BoosterPacks are add-on boards that follow a pin-out standard created by Texas Instruments. The TI and third-party ecosystem of BoosterPacks greatly expands the peripherals and potential applications that you can easily explore with the AM263Px LaunchPad. For a detailed diagram on the pin-out of the AM263Px LaunchPad, refer to [BoosterPack Headers](#).

You can also build your own BoosterPack by following the design guidelines on TI's website. Texas Instruments even helps you promote your BoosterPack to other members of the community. TI offers a variety of avenues for you to reach potential customers with your solutions.

### 1.3.4 Component Identification



**Figure 1-3. AM263Px LaunchPad Top Components Identification**



**Figure 1-4. AM263Px LaunchPad Bottom Components Identification**

## 1.4 Compliance

All components selected meet RoHS and REACH compliance.

Components installed on the product are sensitive to Electrostatic Discharge (ESD). It is recommended this product be used in an ESD controlled environment. This may include a temperature and/or humidity controlled environment to limit the buildup of ESD. It is also recommended to use ESD protection such as wrist straps and ESD mats when interfacing with the product.

The product is used in the basic electromagnetic environment as in laboratory conditions, and the applied standard is as per EN IEC 61326-1:2021.

## 2 Hardware Description

### 2.1 Board Setup

#### 2.1.1 Power Requirements

The AM263Px LaunchPad is powered from a 5V, 3A USB type-C input. The following sections describe the power distribution network topology that supply the AM263Px LaunchPad, supporting components and the reference voltages.

Power supply solutions that are compatible with the AM263Px LaunchPad:

- When using the USB type-C input:
  - 5V, 3A power adapter with USB-C receptacle
  - 5V, 3A power adapter with captive USB-C cable
  - PC USB type-C port that has Power Delivery classification
    - Thunderbolt
    - Battery behind USB logo

	USB 2.0 High Speeds 480 MBit/s	USB 3.0 (USB 3.1 Gen 1) Super Speed 5 GBit/s	USB 3.1 Gen 2 Super Speed Plus 10 GBit/s
Does NOT support Power Delivery			
Does support Power Delivery			
<b>Thunderbolt</b> Does support Power Delivery			

Figure 2-1. USB Type-C Power Delivery Classification

Power supply solutions that are **NOT** compatible with the AM263Px LaunchPad:

- When using USB type-C input:
  - Any USB adapter cables such as:
    - Type-A to type-C
    - micro-B to type-C
    - DC barrel jack to type-C
  - 5V, 1.5A power adapter with USB-C captive cable or receptacle
  - PC USB type-C port not capable of 3A

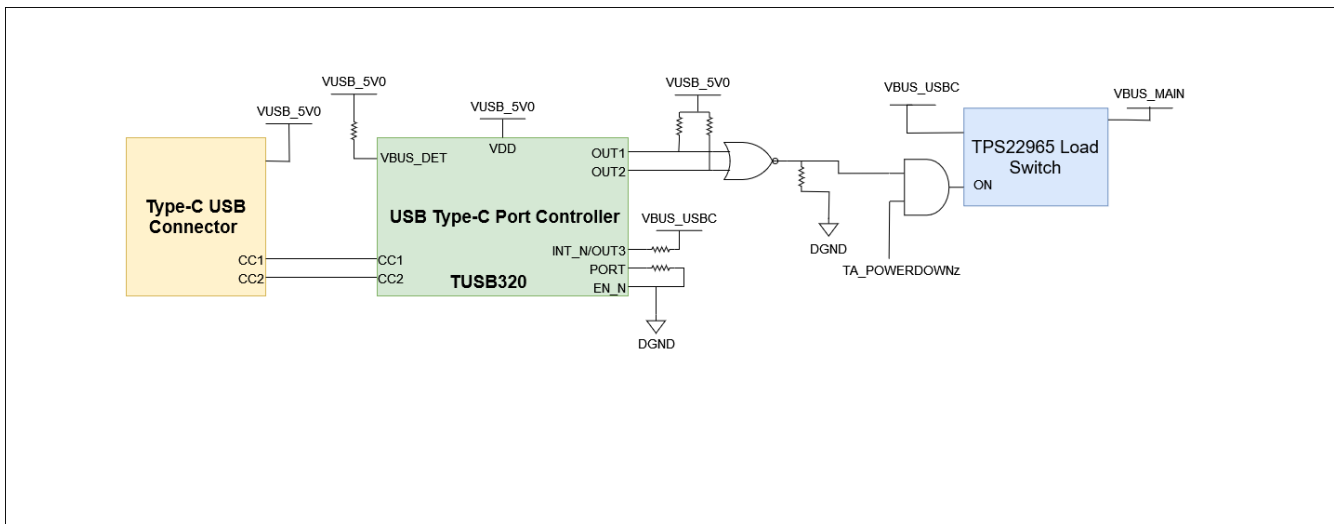
### 2.1.1.1 Power Input Using USB Type-C Connector

The AM263Px LaunchPad is powered through a USB type-C connection. The USB Type-C source should be capable of providing 3A at 5V and should advertise the current sourcing capability through CC1 and CC2 signals. On AM263Px LaunchPad, the CC1 and CC2 from USB type-C connector are interfaced to the port controller IC (TUSB320). This device uses the CC pins to determine port attach and detach, cable orientation, role detection, and port control for Type-C current mode. The CC logic detects the Type-C current mode as default, medium, or high depending on the role detected.

The Port pin is pulled down to ground with a resistor to configure it as upward facing port (UFP) mode. VBUS detection is implemented to determine a successful attach in UFP mode. The OUT1 and OUT2 pins are connected to a NOR gate. Active low on both the OUT1 and OUT2 pins advertises high current (3A) in the attached state which enables the VUSB\_5V0 power switch to provide the VSYS\_5V0 supply which powers other regulators and LDOs.

In UFP mode, the port controller IC constantly presents pull down resistors on both CC pins. The port controller IC also monitors the CC pins for the voltage level corresponding to the Type-C mode current advertisement by the connected DFP. The port controller IC de-bounces the CC pins and waits for VBUS detection before successfully attaching. As a UFP, the port controller device detects and communicates the advertised current level of the DFP to the system through the OUT1 and OUT2 GPIOs.

The AM263Px LaunchPad power requirement is 5V at 3A and if the source is not capable of providing the required power, the output at the NOR gate becomes low that disables the VUSB\_5V0 power switch. Therefore, if the power requirement is not met, all power supplies except VCC3V3\_TA remains in the off state. The board gets powered on completely only when the source can provide 5V at 3A.



**Figure 2-2. Type-C CC Configuration**

**Table 2-1. Current Sourcing Capability and State of USB Type-C Cable**

OUT1	OUT2	Advertisement
H	H	Default current in unattached state
H	L	Default current in attached state
L	H	Medium current (1.5A) in attached state
L	L	High current (3.0A) in attached state

The AM263Px LaunchPad includes a power solution based on discrete regulators for each of the power rails. During the initial stage of the power supply, 5V supplied by the type-C USB connector is used to generate all of the necessary voltages required by the LaunchPad.

Discrete DC-DC buck regulators and LDOs are used to generate the supplies required for the AM263Px system on a chip (SoC) and other peripherals.

**Table 2-2. Voltage Rail Generation**

Component	Reference Designator	Function	Voltage In	Voltage Out
TPS62913	U29	AM263Px Core Digital 1.2V	5.0V	1.2V
TPS74801	U32	System 3.3V	5.0V	3.3V
TSP74801	U30	Ethernet PHY 2.5V	5.0V	2.5V
TPS74801	U31	Ethernet PHY 1.1V	5.0V	1.1V
TPS62177	U36	Test Automation Header 3.3V	5.0V	3.3V

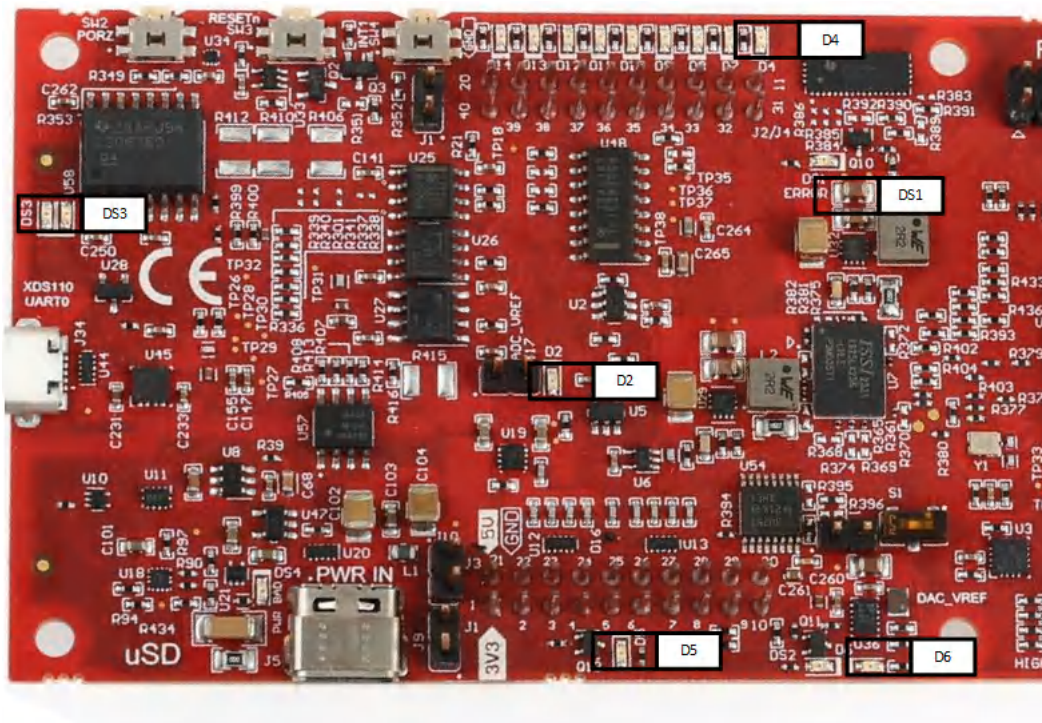


### 2.1.1.2 Power Status LEDs

Multiple power-indication LEDs are provided onboard to indicate to users the output status of major supplies. The LEDs indicate power across various domains.

**Table 2-3. Power Status LEDs**

Name	Default Status	Operation	Function
D2	ON	VSYS_5V0	Power indicator for generated 5V voltage
D4	ON	VSYS_3V3	Power indicator for generated 3.3V voltage
D5	ON	PG_VDD_1V2	Power indicator for generated 1.2V power-good voltage
D6	ON	VSYS_TA_3V3	Power indicator for voltage going to the Test Automation Header
DS1	OFF	SAFETY_ERROR	Power error indication for voltage - VUSB_5V0
D3	OFF	XDS_PROGSTAZ1	LED will glow after micro-B connection is made
DS3	OFF	XDS_PROGSTAZ2	LED will glow to indicate communication over JTAG
DS4	OFF	VUSB_5V0	Power NOT Good (Power Bad)



**Figure 2-3. Power Status LEDs**

### 2.1.1.3 Power Tree

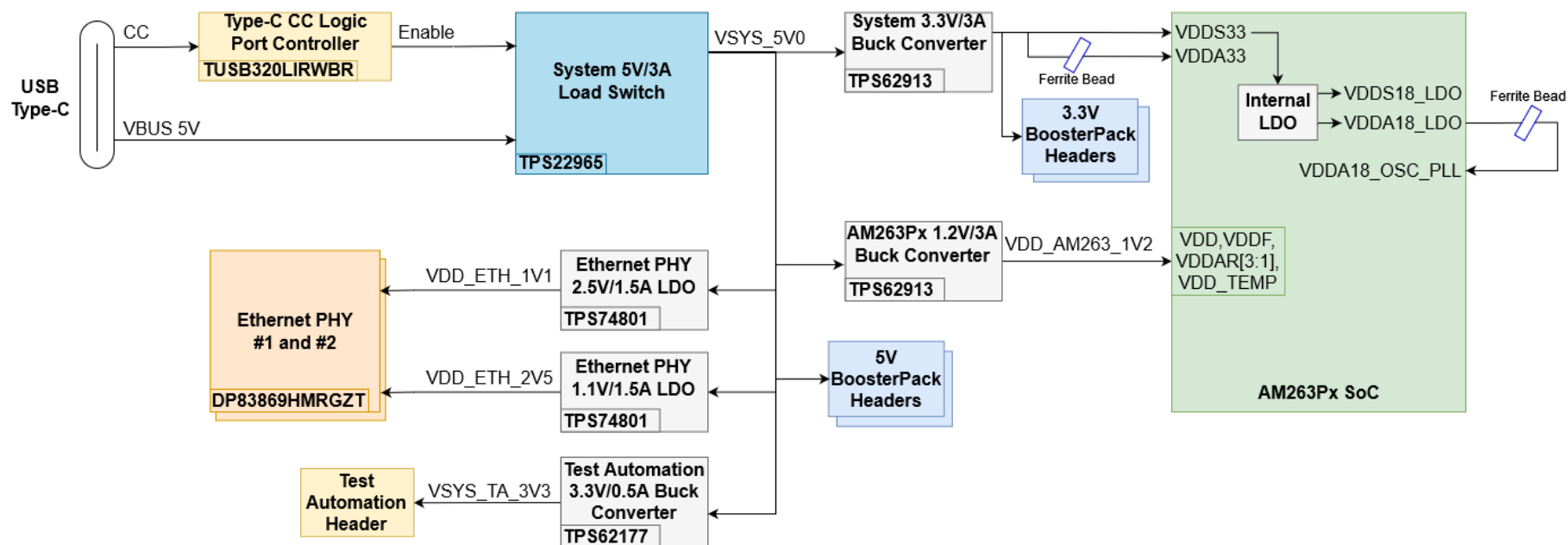
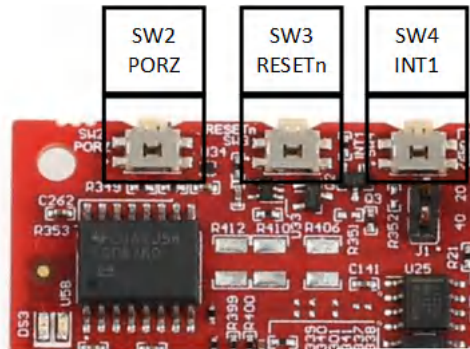


Figure 2-4. Power Tree Diagram of AM263Px LaunchPad

### 2.1.2 Push Buttons

The LaunchPad supports multiple user push buttons that provide reset inputs and user interrupts to the AM263Px SoC.



**Figure 2-5. Push Buttons**

Table 2-4 lists the push buttons that are placed on the top side of the AM263Px LaunchPad.

**Table 2-4. LaunchPad Push Buttons**

Push Button	Signal	Function
SW2	PORz	SoC PORz reset input
SW3	RESETz	SoC warm reset input
SW4	INT1	User Interrupt Signal

### 2.1.3 Boot mode Selection

The boot mode for the AM263Px is selected by a DIP (Dual In-Line Package) switch (SW1) or the test automation header. The test automation header uses an I2C expansion buffer to drive the boot mode when PORz is toggled. The supported boot modes are shown in [Table 2-6](#). The DIP Switch configurations for each boot mode are shown in [Table 2-5](#).

**Note**

As seen in the schematic, enabling (toggling to ON state) a switch pulls the respective SOP pin to GND through a 1kΩ resistor. Thus the Boot mode selection switches' logic table below is logical invert of the corresponding SOP logic levels for a given boot mode, as seen in AM263P Technical Reference Manual.

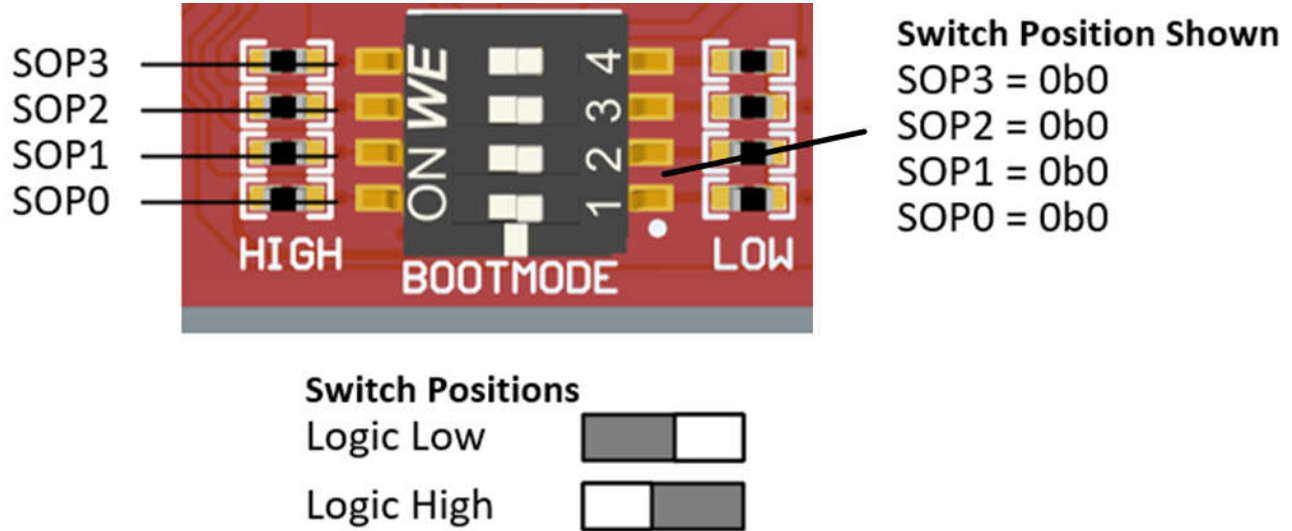


Figure 2-6. Boot mode DIP Switch Positions - LP AM263P SW1 SOP Switches

Table 2-5. Boot mode Selection

Boot mode	SPI0_D0_pad (SOP3 - SW1.4)	SPI0_CLK_pad (SOP2 - SW1.3)	QSPI_D1 (SOP1 - SW1.2)	QSPI_D0 (SOP0 - SW1.1)
OSPI (4S) - Quad Read Mode	1	1	1	1
UART	1	1	1	0
OSPI (1S) - Single Read Mode	1	1	0	1
OSPI (8S) - Octal Read Mode	1	1	0	0
DevBoot	0	1	0	0
xSPI 8D (SFDP)	0	0	1	1
Unsupported boot mode	All other combinations not defined above			

**Table 2-6. Supported Boot modes**

Boot mode/Peripheral	Boot Media/Host	Notes
OSPI (4S) - Quad Read Mode	OSPI Flash	Download and boot SBL from OSPI flash in quad read mode. Attempt Primary SBL, followed by Secondary SBL if primary loading fails.
UART	External Host	Download and boot SBL from UART interface via XMODEM protocol at 115200bps BaudRate.
OSPI (1S) - Single Read Mode	OSPI Flash	Download and boot SBL from OSPI flash in single read mode. Attempt Primary SBL, followed by Secondary SBL if primary loading fails.
OSPI (8S) - Octal Read Mode	OSPI Flash	Download and boot SBL from OSPI flash in octal read mode. Attempt Primary SBL, followed by Secondary SBL if primary loading fails.
xSPI 8D (SFDP)	OSPI Flash	Read SFDP table for read command, download and boot SBL from OSPI flash in 8D mode. Attempt Primary SBL, followed by Secondary SBL if primary loading fails.
DevBoot	N/A	No SBL. Used for development purposes only.

### 2.1.4 IO Expander

AM263Px LaunchPad has an TCA6416ARTWR IO Expander, that provides general-purpose remote I/O expansion and bidirectional voltage translation for processors through I2C communication, an interface consisting of serial clock (SCL), and serial data (SDA) signals.

The TCA6416A's digital core consists of eight 8-bit data registers: two Configuration registers (input or output selection), two Input Port registers, two Output Port registers, and two Polarity Inversion registers. At power on or after a reset, the I/Os are configured as inputs. However, the system controller can configure the I/Os as either inputs or outputs by writing to the Configuration registers. The data for each input or output is kept in the corresponding Input Port or Output Port register. The polarity of the Input Port register can be inverted with the Polarity Inversion register. All registers can be read by the system controller. In AM263P SoC, the communication with IO Expander is done through I2C1 bus. The signals that are coming out of the IO Expander shown in [IO Expander](#). Please refer to [TCA6416ARTWR-Datasheet](#) for programming guide of TCA6416ARTWR.



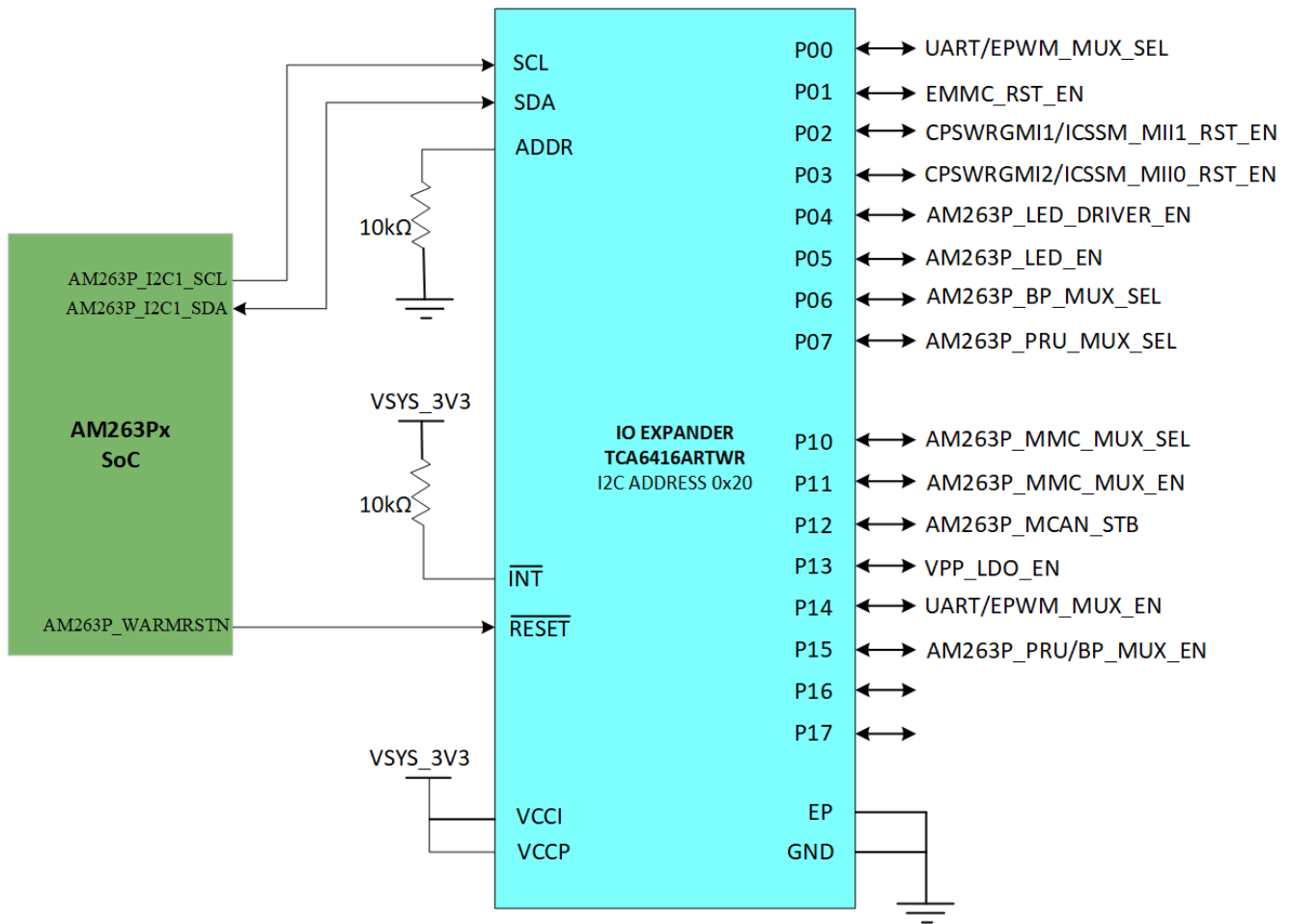


Figure 2-7. IO Expander

## 2.2 Functional Block Diagram

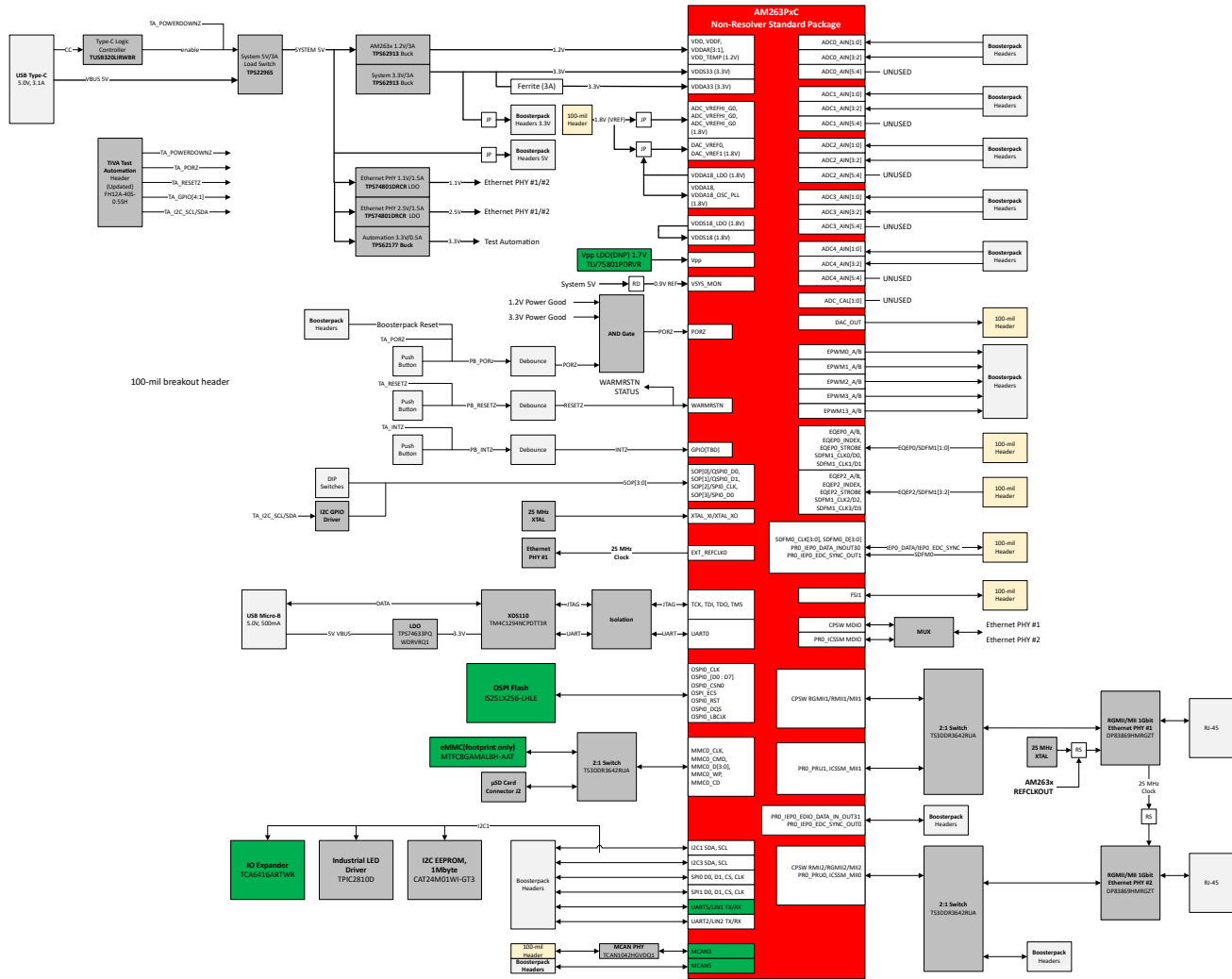


Figure 2-8. AM263Px LaunchPad Functional Block Diagram

## 2.3 GPIO Mapping

**Table 2-7. GPIO Mapping Table**

<b>GPIO Description</b>	<b>GPIO</b>	<b>Functionality</b>	<b>Net Name</b>	<b>Active Status</b>
CPSW RGMII1/MII1 MUX select	GPIO105	GPIO	RGMI1_ICSSM_MUX_SEL_GPIO105	LOW
SD Card Load Switch Enable	GPIO122	GPIO	AM263P_SD_ENABLE_GPIO122	LOW
Interrupt To SoC	GPIO123	Interrupt	AM263P_INT1_PB_GPIO123	LOW

## 2.4 Reset

Figure 2-9 shows the reset architecture of the AM263Px LaunchPad

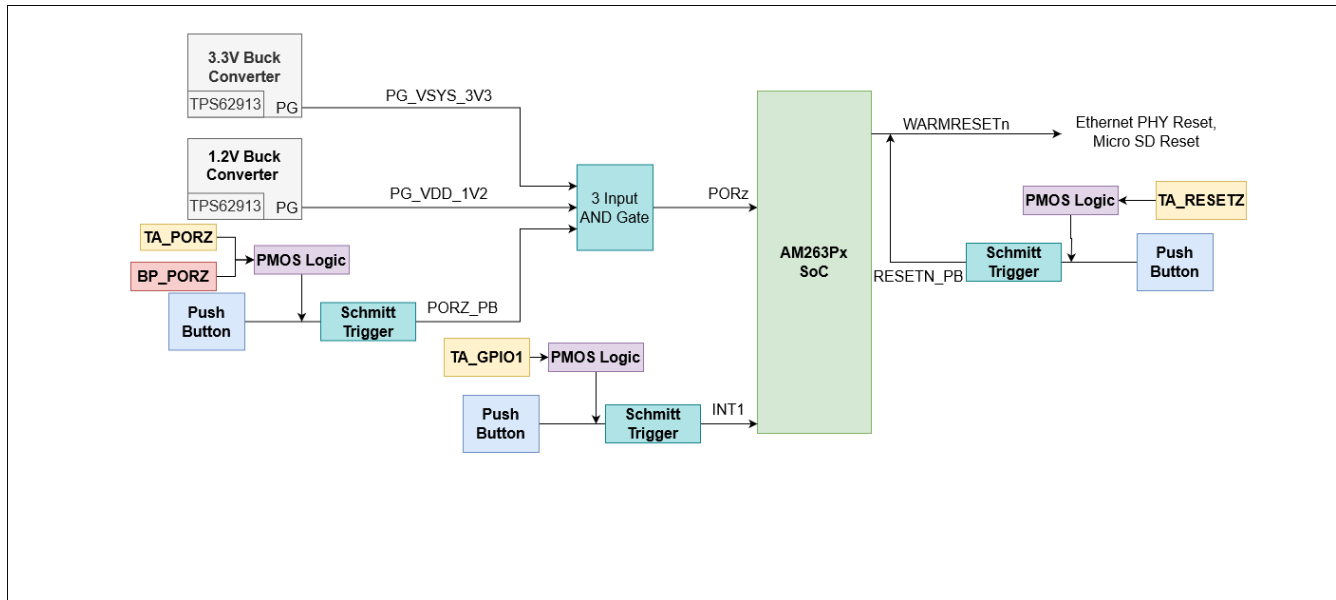


Figure 2-9. Reset Architecture

The AM263Px LaunchPad has the following resets:

- PORz is the Power On Reset
- WARMRESETn is the warm reset

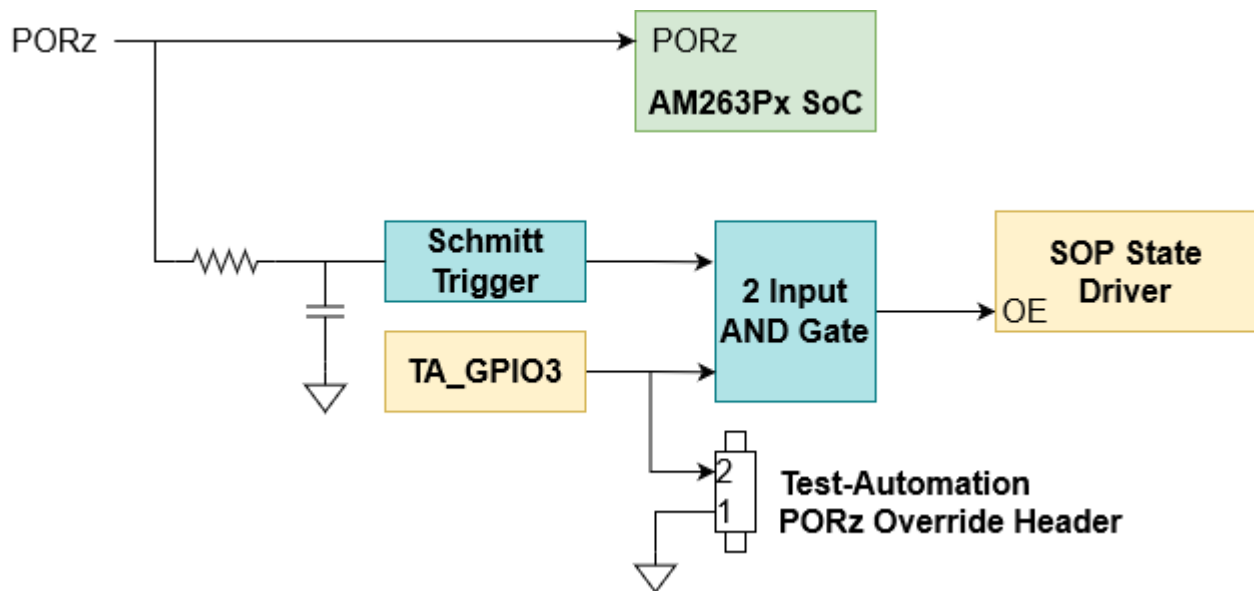


Figure 2-10. PORz Reset Signal Tree

The PORz signal is driven by a 3-input AND gate that generates a power on reset for the MAIN domain when:

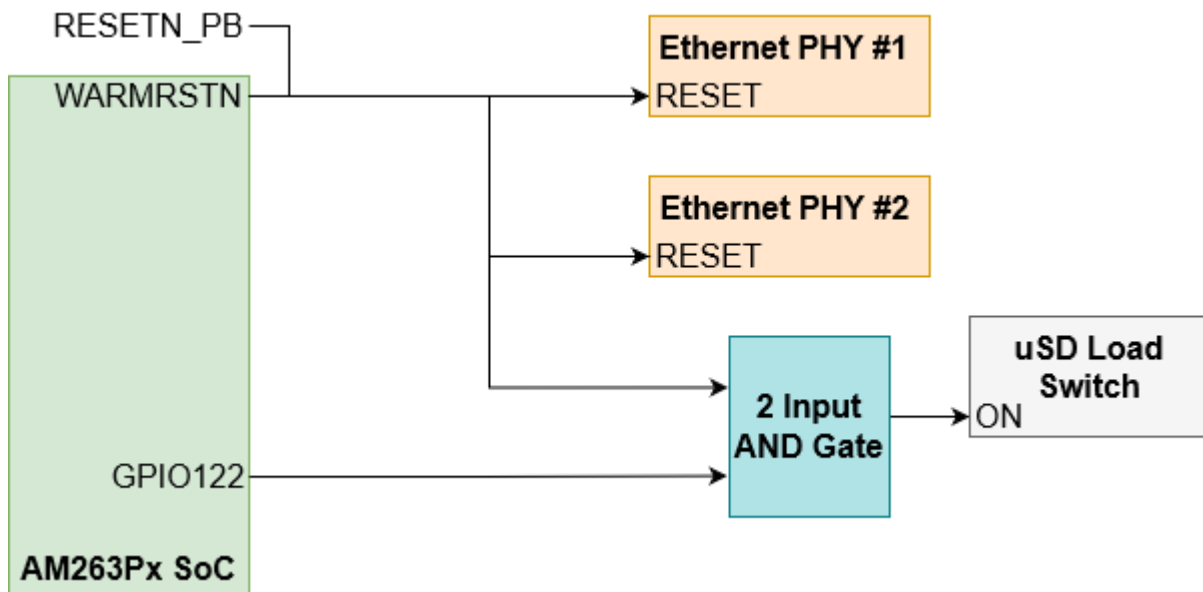
- The 3.3V buck converter (TPS62913) power good output is driven low by having an output voltage that is below the power-good threshold.
- The 1.2V buck converter (TPS62913) power good output is driven low by having an output voltage that is below the power-good threshold.
- The user push button (SW2) is pressed.

- A P-Channel MOSFET gate's signal is logic LOW which causes  $V_{GS}$  of the PMOS to be less than zero and so the PORz signal connects to the PMOS drain which is tied directly to ground. The signals that can create the logic LOW input to the PMOS gate are:
  - TA\_PORZ output from the Test Automation header
  - BP\_PORZ output from either of the BoosterPack sites.

The PORz signal is tied to:

- AM263Px SoC PORz input
- Boot mode State Driver(U4)'s output enable input
  - There is an RC filter to create a 1ms delay from GND to 3.0V such that the SOP State Driver's output enable input is low longer than the required SOP hold time following a PORz de-assertion.

There is a Test-Automation PORz Override header that enables the ability to hold TA\_GPIO3 low when a jumper is installed. This enables the boot mode Control from the Test Automation Header.



**Figure 2-11. WARMRESETn Reset Signal Tree**

The WARMRESETn signal creates a warm reset to the MAIN domain when:

- The user push button (SW3) is pressed.
- The Test Automation Header outputs a logic LOW signal (TA\_RESETz) to a P-Channel MOSFET gate which causes  $V_{GS}$  of the PMOS to be less than zero and so the RESETz signal connects to the PMOS drain which is tied directly to ground.

The WARMRESETn signal is tied to:

- AM263Px SoC WARMRESETN output
- RESETN\_PB signal that is created from push button + PMOS logic
- Micro SD Load Switch control input via a 2 input AND Gate with an AM263Px SoC driven GPIO signal (GPIO122)
- Both Ethernet PHYs reset input

The AM263Px LaunchPad also has an external interrupt to the SoC , INT1, that occurs when:

- The user push button (SW4) is pressed.
- The Test Automation Header outputs a logic LOW signal (TA\_GPIO1) to a P-Channel MOSFET gate which causes  $V_{GS}$  of the PMOS to be less than zero and so the INTn signal connects to the PMOS drain which is tied directly to ground.



## 2.5 Clock

The AM263Px SoC requires a 25MHz clock input for XTAL\_XI. The AM263Px LaunchPad uses a 25MHz crystal for the SoC clock source. The LaunchPad also has two 25MHz Crystals onboard for the Ethernet PHY clocking. The SoC clock signal output CLKOUT0 can be used as a clock source for Ethernet PHY #1 by removing the resistors mounted for XTAL\_XI and XTAL\_XO from the 25MHz Ethernet PHY #1 Crystal and mounting the appropriate resistor for the CLKOUT0 signal to be routed to the XI pin of the Ethernet PHY.

The Ethernet PHY #1 clock signal output ETH1\_CLKOUT can be used as a clock source for Ethernet PHY #2 by removing the resistors mounted for XTAL\_XI and XTAL\_XO from the 25MHz Ethernet PHY #2 Crystal and mounting the appropriate resistor for the ETH1\_CLKOUT signal to be routed to the XI pin of Ethernet PHY #2.

The LaunchPad also requires a 16MHz clock source for the XDS110 for UART-USB JTAG support.

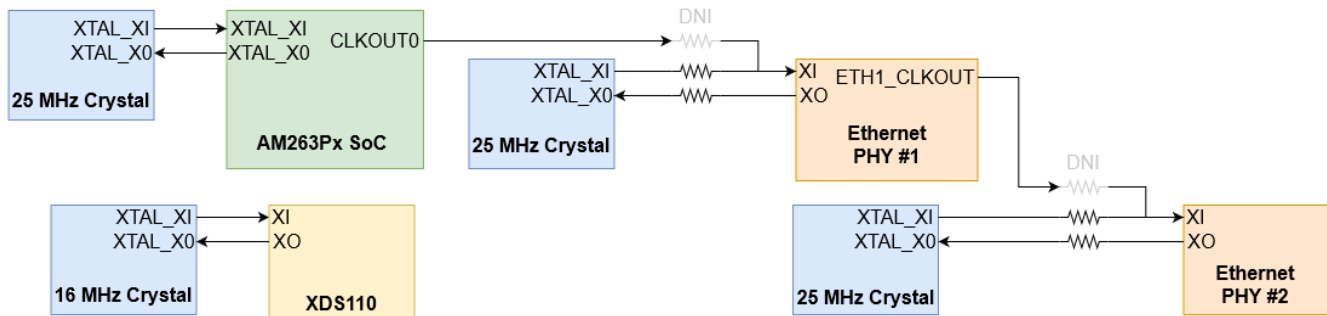


Figure 2-12. AM263Px LaunchPad Clock Tree

## 2.6 Memory Interfaces

### 2.6.1 OSPI

The AM263Px LaunchPad has a 256 Mb OSPI Flash memory device (IS25LX256-LHLE), which is connected to the OSPI0 interface of the AM263Px SoC. The OSPI supports single data rates(SDR) and double data rates(DDR) with memory speeds up to 133MHz. The OSPI flash is powered by the 3.3V system supply.

The OSPI0\_D0/D1 signals are also used for boot mode control logic. There are 10KΩ resistors used to isolate the boot mode control logic after the value is latched.

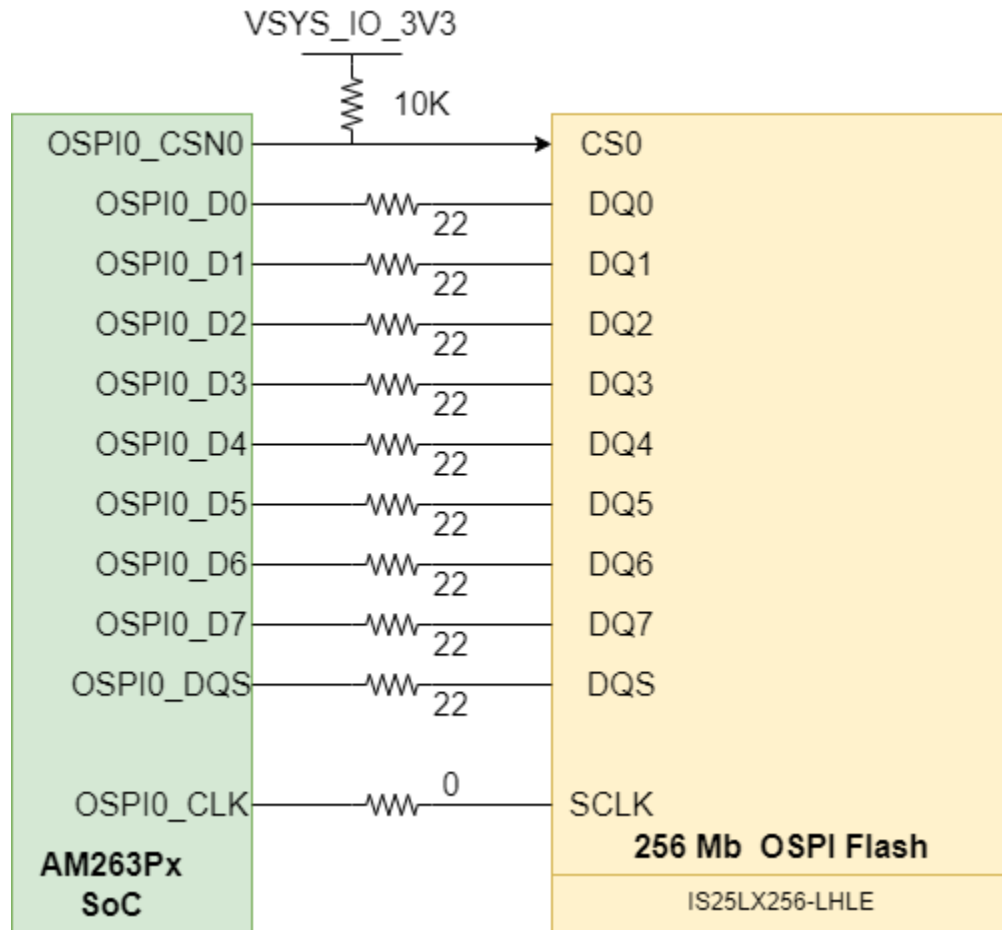


Figure 2-13. OSPI Flash Interface

#### Note

AM263P\_OSPI0\_DQS(UART1\_RXD) and AM263P\_OSPI0\_LBCLK(UART1\_TXD) net names are wrongly swapped in the schematics of LP-AM263P Revision E2. As per datasheet OSPI0\_DQS must be connected to M3 ball pin and OSPI0\_LBCLKO must be connected to L3 Ball pin. This has been corrected in Revision A of LP-AM263P.

Refer to [OSPI DQS and LBCLK nets swap](#) for more details.

## 2.6.2 MMC

The AM263Px LaunchPad provides a micro SD card interface that is mapped to the MMC0 instance of the AM263Px SoC.

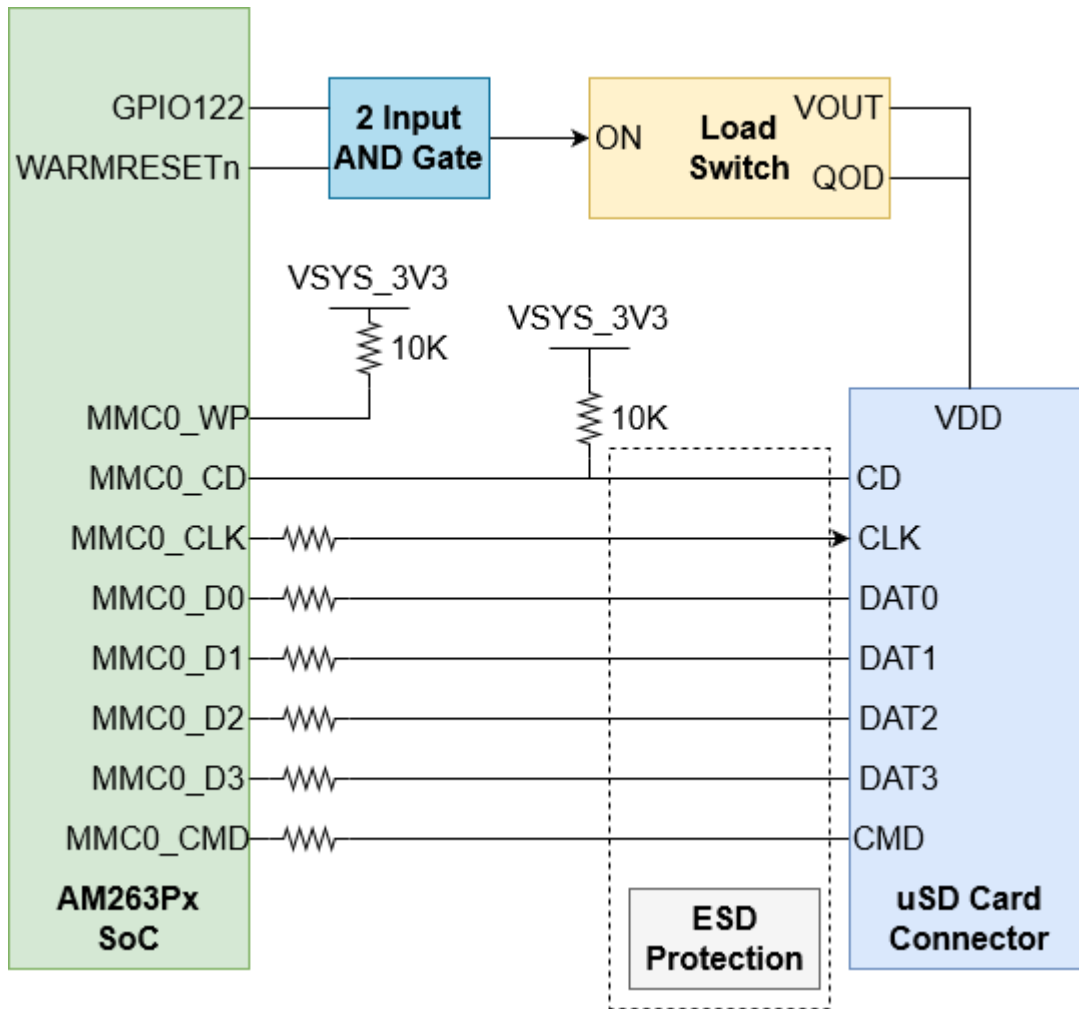


Figure 2-14. Micro SD Card Connector

A load switch (TPS22918TDBVTQ1) is used to power the micro SD card connector. The load switch is driven by the output of a 2-input AND gate between WARMRESETn and the SD Card enable GPIO (GPIO122) to power cycle the card upon reset. The load switch uses quick output discharge (QOD) to make sure that the supply voltage reaches <10% of nominal value during reset.

Inline ESD protection is provided for the MMC signals in the form of a six channel transient voltage suppressor device (TPD6E001RSER) and two channel transient voltage suppressor device (TPD2E001DRLR).

The Write Protect (WP) and Card Detect (CD) signals of the SD card connector are pulled up to the 3.3V System voltage supply.

A series termination resistor is provided for all MMC signals besides CD.

### 2.6.3 eMMC

The AM263Px LaunchPad has a eMMC footprint that is mapped to the MMC0 instance of the AM263Px SoC, muxed through U53 MUX. The current eMMC footprint is considering the eMMC part MTFC8GAMALBH-AAT. Users can mount the same part, or pin compatible ones for evaluating the eMMC interface.

---

#### Note

The current eMMC footprint on the LP-AM263P board has a mismatch of the AM263P\_EMMC0\_CLK\_MUX and AM263P\_EMMC0\_CMD\_MUX nets, where in they are swapped with each other wrongly. This needs to be fixed through a hardware modification of the board, before evaluating eMMC. Please refer to [eMMC CMD and CLK nets swap](#) for more details.

---

### 2.6.4 Board ID EEPROM

The AM263Px LaunchPad has a I2C based 1Mbit EEPROM (CAT24M01WI-GT3) to store board configuration details. The Board ID EEPROM is connected to the I2C1 interface of the AM263Px SoC. The default I2C address of the EEPROM is set to 0x52 by pulling up the address pin A1 and pulling down the address pin A2 to ground. The Write Protect pin for the EEPROM is by default pulled down to ground and therefore Write Protect is disabled.

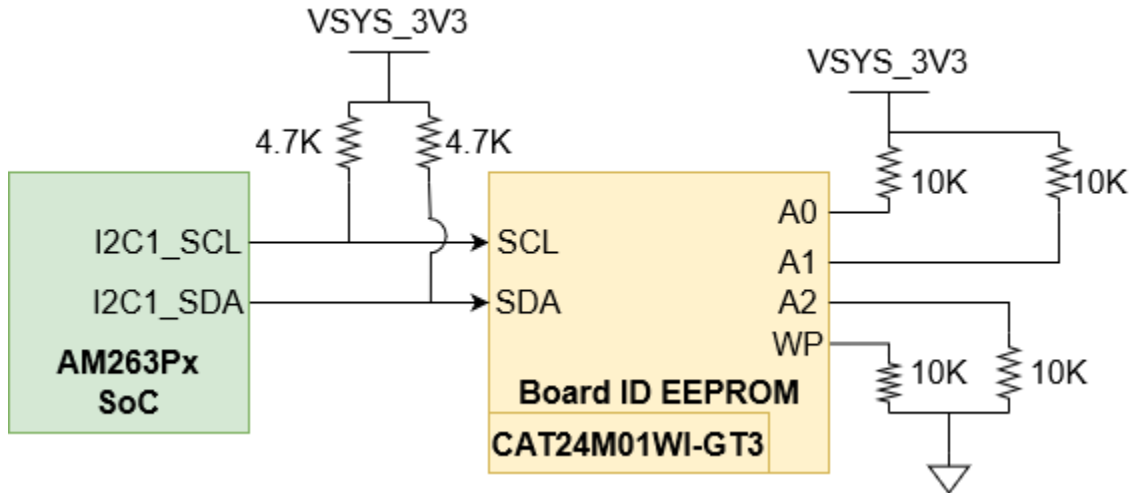


Figure 2-15. Board ID EEPROM



## 2.7 Ethernet Interface

### 2.7.1 Ethernet PHY #1 - CPSW RGMII/ICSSM

#### Note

The PRU internal pinmux mapping provided in the TRM is part of the original hardware definition of the PRU. However, due to the flexibility provided by the IP and associated firmware configurations, this is not necessarily a hard requirement. The first PRU implementation for AM65x had the MII TX pins swapped during initial SOC integration and this convention as maintained for subsequent PRU revisions to enable firmware reuse. To make use of the SDK firmware, use the SYSCONFIG generated PRU pin mapping.

The AM263Px LaunchPad utilizes a 48-pin Ethernet PHY (DP83869HMRGZT) connected to either CPSW RGMII or one on-die Programmable Real-time Unit and Industrial Communication Sub System (PRU-ICSS). There is a 2:1 mux that selects between the RGMII or PRU-ICSS signals. The PHY is configured to advertise 1-Gb operation. The Ethernet data signals of the PHY are terminated to an RJ45 connector. The RJ45 connector is used on the board for Ethernet 10/100/1000Mbps connectivity with integrated magnetics and LEDs for link and activity indication.

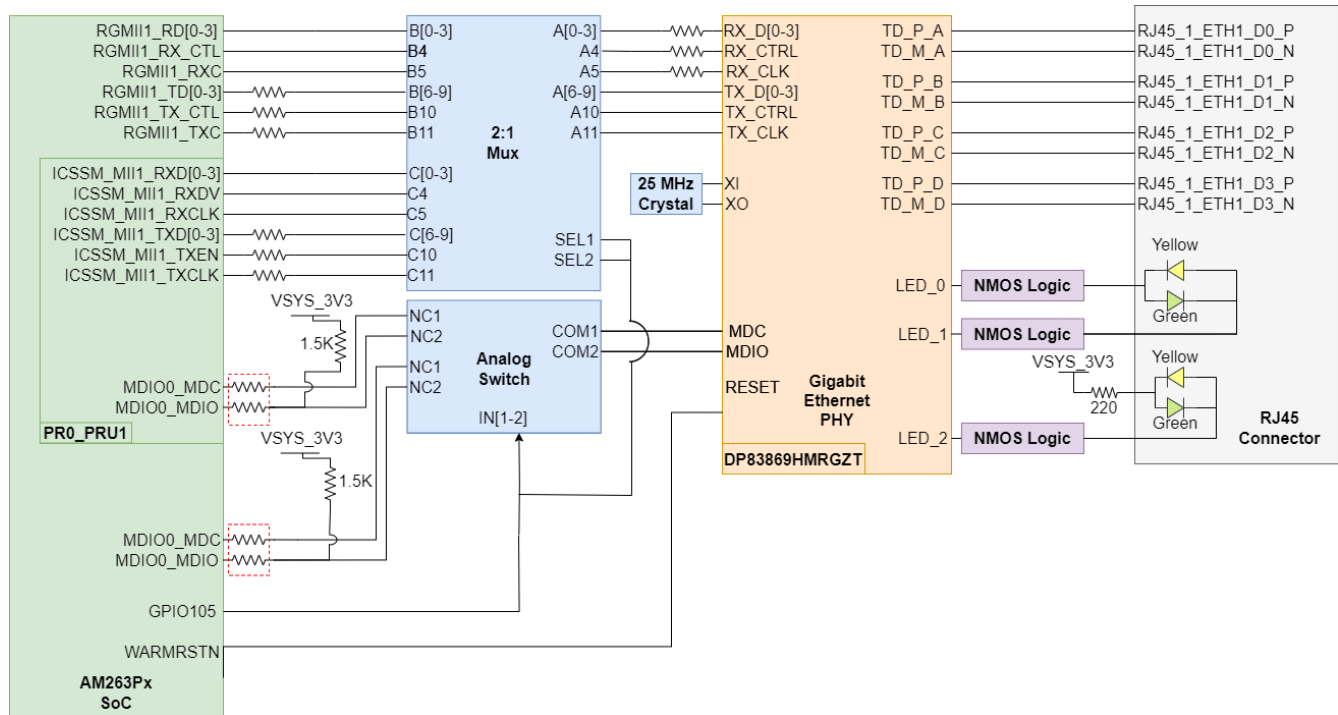


Figure 2-16. Ethernet PHY #1

The Ethernet PHY requires three separate power sources. VDDIO is the 3.3V, system generated supply. There are dedicated LDO's for the 1.1V and 2.5V supplies for the Ethernet PHY.

There are series termination resistors on the transmit clock and data signals located near the SoC. There are series termination resistors on the receive clock and data signals near the Ethernet PHY.

The MDIO signal from the SoC to the PHY require 1.5kΩ pullup resistors to the 3.3V system supply voltage for proper operation. There is an analog switch (TS5A23159DGSR) that selects between the CPSW MDIO/MDC and the ICSSM MDIO/MDC signals to be routed to the Ethernet PHY.

Both the 2:1 mux and analog switch are controlled by a GPIO signal that selects between CPSW RGMII and ICSSM signals.

**Table 2-8. Ethernet PHY #1 CPSW/ICSSM Select**

GPIO105	Condition	Function of Mux
LOW	RGMII CPSW Selected	Port A ↔ Port B
HIGH	ICSSM Selected	Port A ↔ Port C

The reset input for the Ethernet PHY is controlled by the WARMRESET AM263Px SoC output signal.

The Ethernet PHY uses many functional pins as strap option to place the device into specific modes of operation.

**Table 2-9. Ethernet PHY #1 Strapping Resistors**

Functional Pin	Default Mode	Mode in LaunchPad	Function
RX_D0	0	3	PHY address: 0011
RX_D1	0	0	
JTAG_TDO/GPIO_1	0	0	RGMII to Copper
RX_D3	0	0	
RX_D2	0	0	
LED_0	0	0	Auto-negotiation, 1000/100/10 advertised, auto MDI-X
RX_ER	0	0	
LED_2	0	0	
RX_DV	0	0	Port Mirroring Disabled

**Note**

Each strap pin has an internal pull down resistance of 2.49kΩ

**Note**

RX\_D0 and RX\_D1 are on a 4-level strap resistor mode scheme. All other signals are 2-level strap resistor modes.

### 2.7.2 Ethernet PHY #2 - CPSW RGMII/ICSSM

#### Note

The PRU internal pinmux mapping provided in the TRM is part of the original hardware definition of the PRU. However, due to the flexibility provided by the IP and associated firmware configurations, this is not necessarily a hard requirement. The first PRU implementation for AM65x had the MII TX pins swapped during initial SOC integration and this convention was maintained for subsequent PRU revisions to enable firmware reuse. To make use of the SDK firmware, use the SYSCONFIG generated PRU pin mapping.

The AM263Px LaunchPad utilizes a 48-pin Ethernet PHY (DP83869HMRGZT) connected to either CPSW RGMII or one on-die Programmable Real-time Unit and Industrial Communication Sub System (PRU-ICSS). The RGMII CPSW port and ICSSM are internally pinmuxed on the AM263Px SoC. For more information on the internal muxing of signals refer to [Pinmux Mapping](#). The PHY is configured to advertise 1-Gb operation. The Ethernet data signals of the PHY are terminated to an RJ45 connector. The RJ45 connector is used on the board for Ethernet 10/100/1000Mbps connectivity with integrated magnetics and LEDs for link and activity indication.

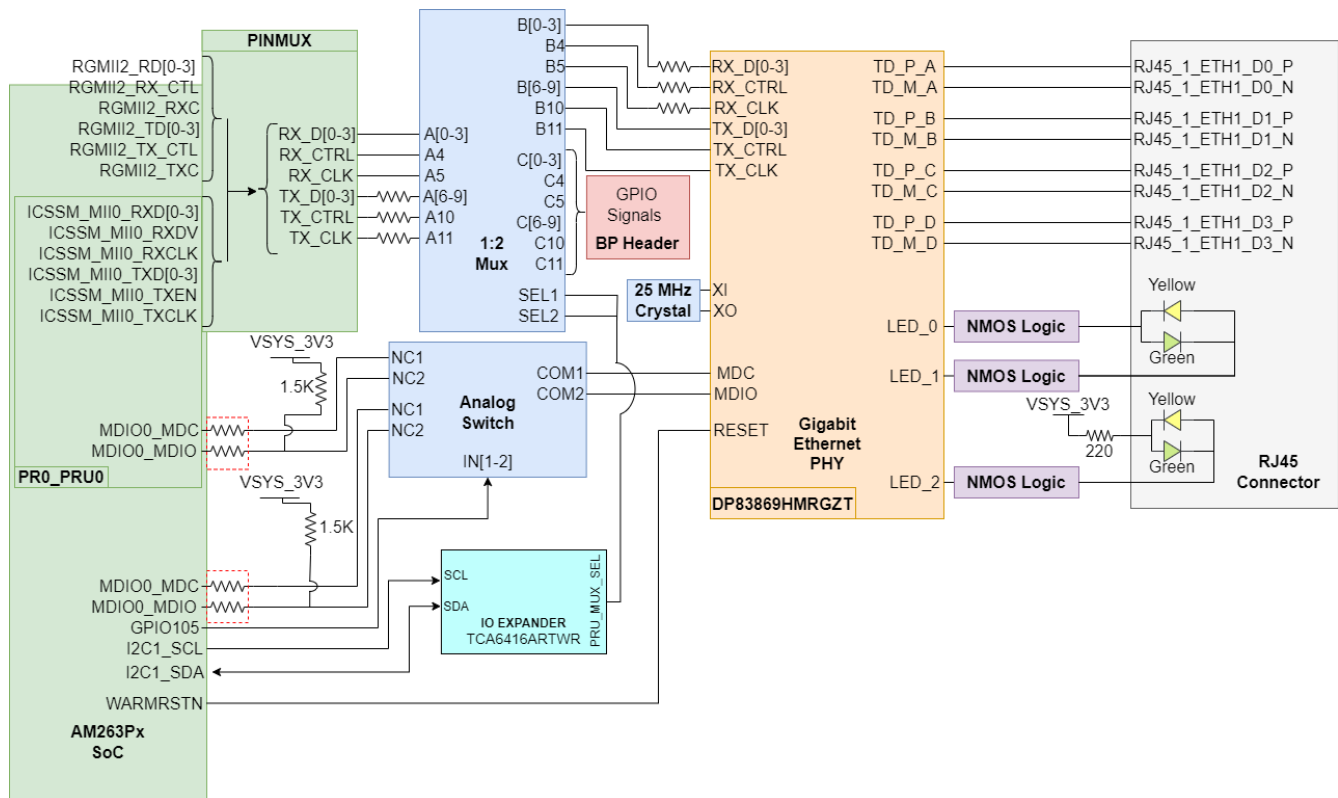


Figure 2-17. Ethernet PHY #2

The Ethernet PHY requires three separate power sources. VDDIO is the 3.3V, system generated supply. There are dedicated LDOs for the 1.1V and 2.5V supplies for the Ethernet PHY.

There are series termination resistors on the transmit clock and data signals located near the SoC. There are series termination resistors on the receive clock and data signals near the Ethernet PHY.

The MDIO signal from the SoC to the PHY require 1.5kΩ pullup resistors to the 3.3V system supply voltage for proper operation. There is an analog switch (TS5A23159DGSR) that selects between the CPSW MDIO/MDC and the ICSSM MDIO/MDC signals to be routed to the Ethernet PHY.

AM263Px internal Pinmux is used to select between CPSW RGMII and ICSSM signals. The signals are then routed to a 1:2 mux (TS3DDR3812RUAR) that selects between mapping the signals to the Ethernet PHY or the BP headers in the case that the PRU GPIO signals are being used in a BoosterPack application. There is an AM263Px SoC GPIO select signal that drives the 1:2 mux.

**Table 2-10. Ethernet PHY #2 CPSW/ICSSM Select**

PRU_MUX_SEL	Condition	Function of Mux
LOW	Ethernet PHY Selected	Port A ↔ Port B
HIGH	BoosterPack header Selected	Port A ↔ Port C

The reset input for the Ethernet PHY is controlled by the WARMRESET AM263Px SoC output signal.

The Ethernet PHY uses many functional pins as strap option to place the device into specific modes of operation.

**Table 2-11. Ethernet PHY #2 Strapping Resistors**

Functional Pin	Default Mode	Mode in LP	Function
RX_D0	0	0	PHY address: 1100
RX_D1	0	3	
JTAG_TDO/GPIO_1	0	0	RGMII to Copper
RX_D3	0	0	
RX_D2	0	0	
LED_0	0	0	Auto-negotiation, 1000/100/10 advertised, auto MDI-X
RX_ER	0	0	
LED_2	0	0	Port Mirroring Disabled
RX_DV	0	0	

**Note**

Each strap pin has an internal pull down resistance of 2.49kΩ

**Note**

RX\_D0 and RX\_D1 are on a 4-level strap resistor mode scheme. All other signals are 2-level strap resistor modes.

### 2.7.3 LED Indication in RJ45 Connector

The AM263Px LaunchPad has two RJ45 network ports for the CPSW RGMII and ICSSM signals of the AM263Px SoC. Each RJ45 connector contains two bi-color LEDs that are used to indicate link and activity.

RJ45 Connector LED indication for the Ethernet PHY #1:

**Table 2-12. Ethernet PHY #1 RJ45 Connector LED indication**

LED	Color	Indication
Right LED	Green	Ethernet PHY power established
	Yellow	Transmit or Receive activity
Left LED	Green	Link OK
	Yellow	1000BT link is up

RJ45 Connector LED indication for the Ethernet PHY #2:

**Table 2-13. Ethernet PHY #2 RJ45 Connector LED indication**

LED	Color	Indication
Right LED	Green	Ethernet PHY power established
	Yellow	Transmit or Receive activity
Left LED	Green	Link OK
	Yellow	1000BT link is up



## 2.8 I2C

The AM263Px LaunchPad uses two AM263Px SoC inter-integrated circuit (I2C) ports to operate as a controller for various targets. I2C data and clock lines needs to be pulled up to the 3.3V system voltage supply to enable communication.

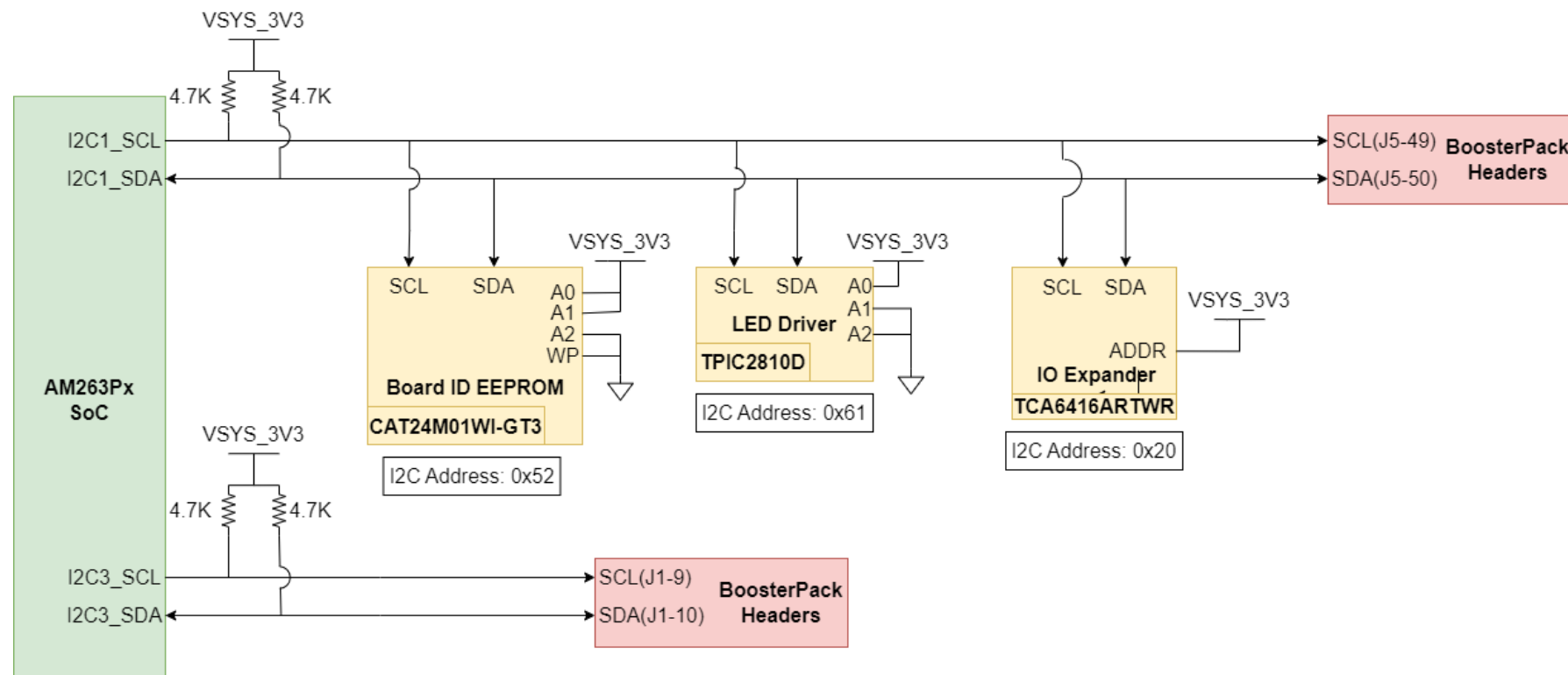


Figure 2-18. I2C Targets

Table 2-14. I2C Addressing

Target	I2C Instance	I2C Address Bit Description	Device Addressing	LaunchPad Config.	I2C Address
Board ID EEPROM	I2C1	The first 4 bits of the device address are set to 1010, the next two are set by the A2 and A1 pins, the seventh bit, a16, is the most significant internal address bit	0b10110[A2][A1][a16] A1 is connected to 3.3V supply A2 is connected to ground	0b1010010	0x52
LED Driver	I2C1	The first four bits of the target address are 1100, the following three are determined by A2, A1, and A0	0b1100[A2][A1][A0] A2/A1 are connected to ground A0 is connected to 3.3V supply	0b1100001	0x61
BoosterPack Headers	I2C1, I2C3	Dependent on target			

**Table 2-14. I2C Addressing (continued)**

Target	I2C Instance	I2C Address Bit Description	Device Addressing	LaunchPad Config.	I2C Address
Boot mode IO Expander	I2C1	The first 6 bits of the target address are set to 010000, the next bit is determined by the addr pin of the IO expander	IO_ADDR pin connected to 3.3V supply	0b0100001	0x21
IO Expander	I2C1	The first 6 bits of the target address are set to 010000, the next bit is determined by the addr pin of the IO expander	IO_ADDR pin connected to 3.3V supply	0b0100001	0x20

---

**Note**

Underlined address bits are fixed based on the device addressing and cannot be configured.

---

## 2.9 Industrial Application LEDs

The AM263Px LaunchPad has an LED Driver (TPIC2810D) that is used for Industrial Communication LEDs. The driver is connected to eight green LEDs, and the driver has an I2C address of 0x61.

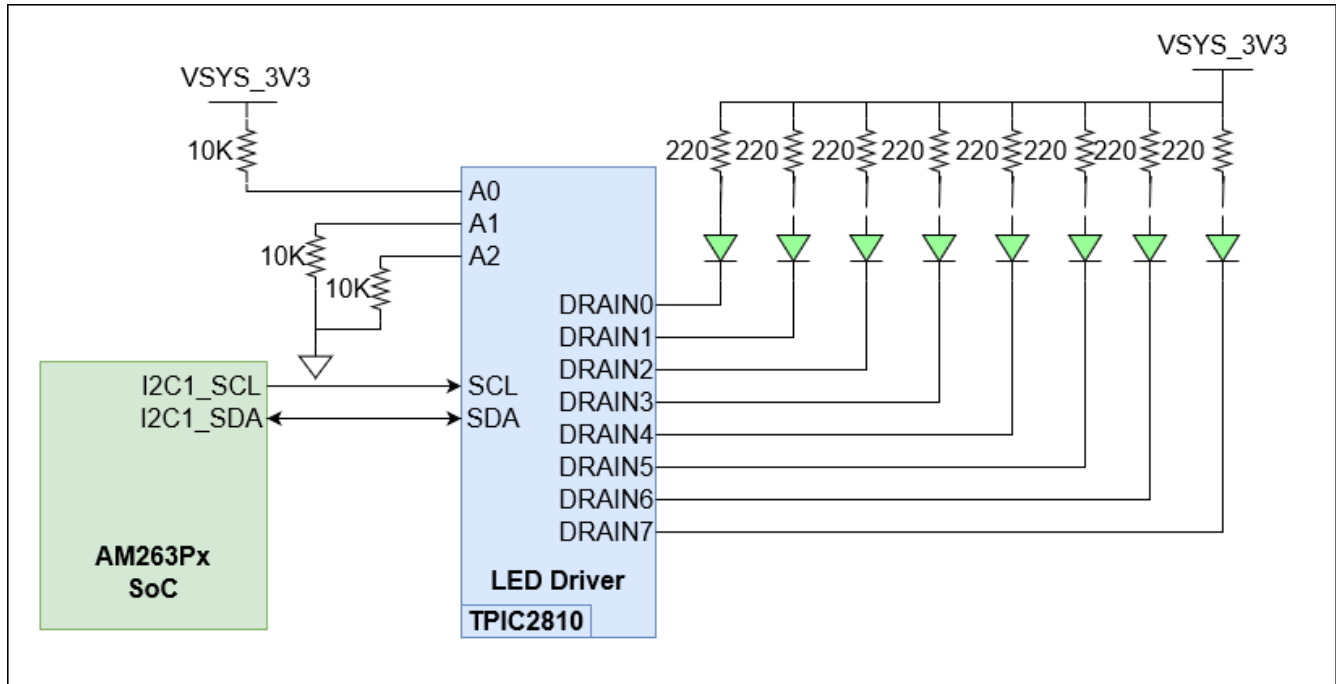


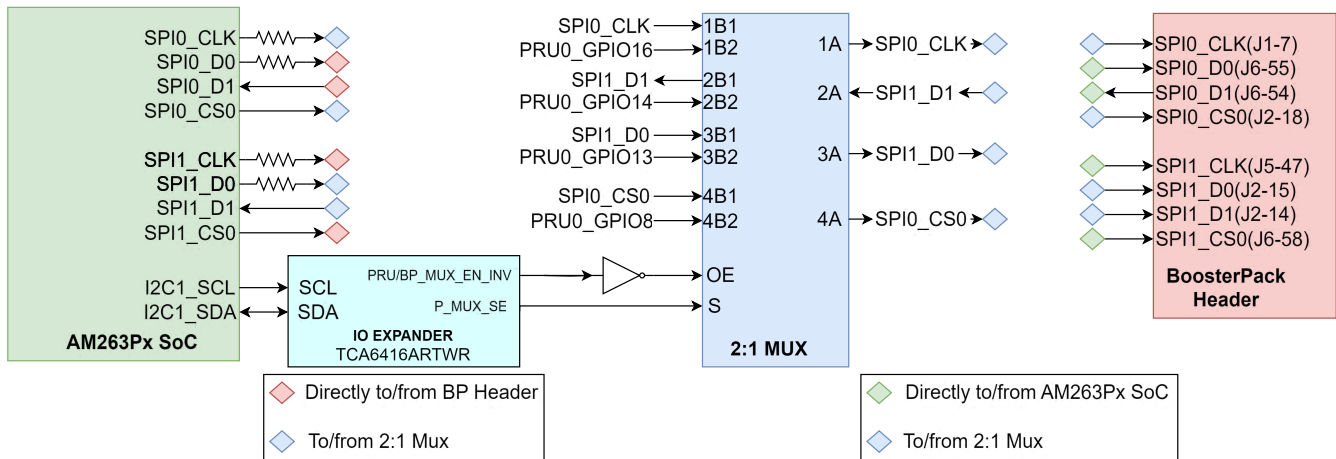
Figure 2-19. Industrial Application I2C LED Array

## 2.10 SPI

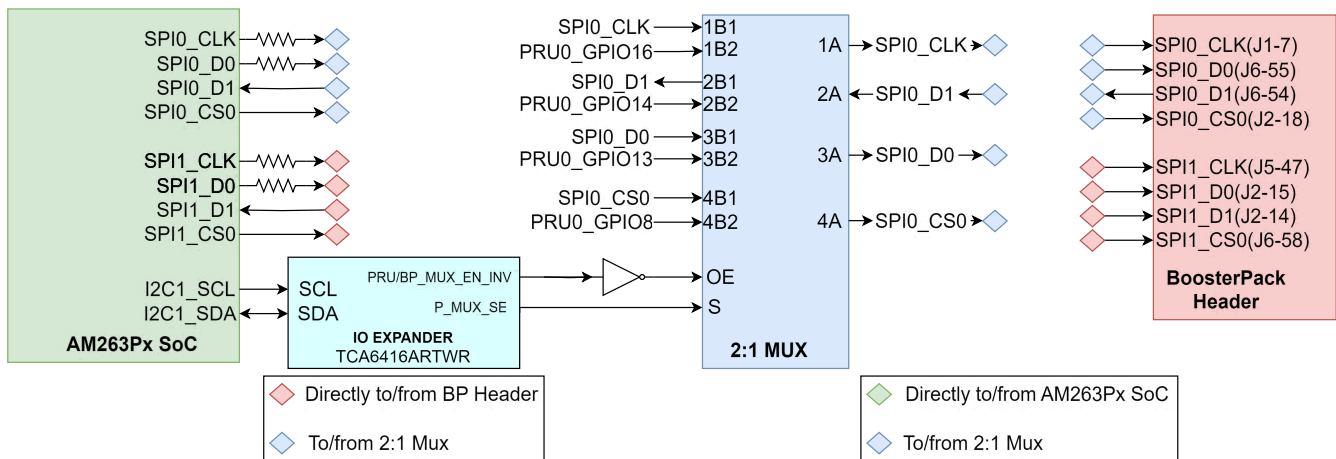
The AM263Px LaunchPad maps two SPI instances (SPI0, SPI1) from the AM263Px SoC to the BoosterPack Headers. Series termination resistors are placed near the SoC for each SPI clock and SPI D0 signal. There is a 2:1 mux (SN74CB3Q3257PWR) that is responsible for selecting SPI signals for proper function. The mux is driven by two GPIO signals that are generated from the AM263Px SoC.

**Table 2-15. SPI Mux**

Output Enable (OE)	Select (S)	Input/Output	Function
Low	Low	A ↔ B1	A port = B1 port
Low	High	A ↔ B2	A port = B2 port
High	X	Hi-Z	Disconnect



**Figure 2-20. SoC SPI to BoosterPack - LP-AM263P RevE2**



**Figure 2-21. SoC SPI to BoosterPack - LP-AM263P RevA**

## 2.11 UART

The AM263Px LaunchPad uses the XDS110 as a USB2.0 to UART bridge for terminal access. UART0 transmit and receive signals of the AM263Px SoC are mapped to the XDS110 with a dual channel isolation buffer (ISO7721DR) for translating from the 3.3V IO voltage supply to the 3.3V XDS supply. The XDS110 is connected to a micro-B USB connector for the USB 2.0 signals. ESD protection is provided to the USB 2.0 signals by a transient voltage suppression device (TPD4E02B04DQAR). The micro-B USB connector's VBUS 5V power is mapped to a low dropout regulator (TPS79601DRBR) to generate the 3.3V XDS110 supply. A separate 3.3V supply for the XDS110 allows for the emulator to maintain a connection when power to the LaunchPad is removed.

Separate UART instances (UART2 & UART5) are mapped directly to the BoosterPack header.

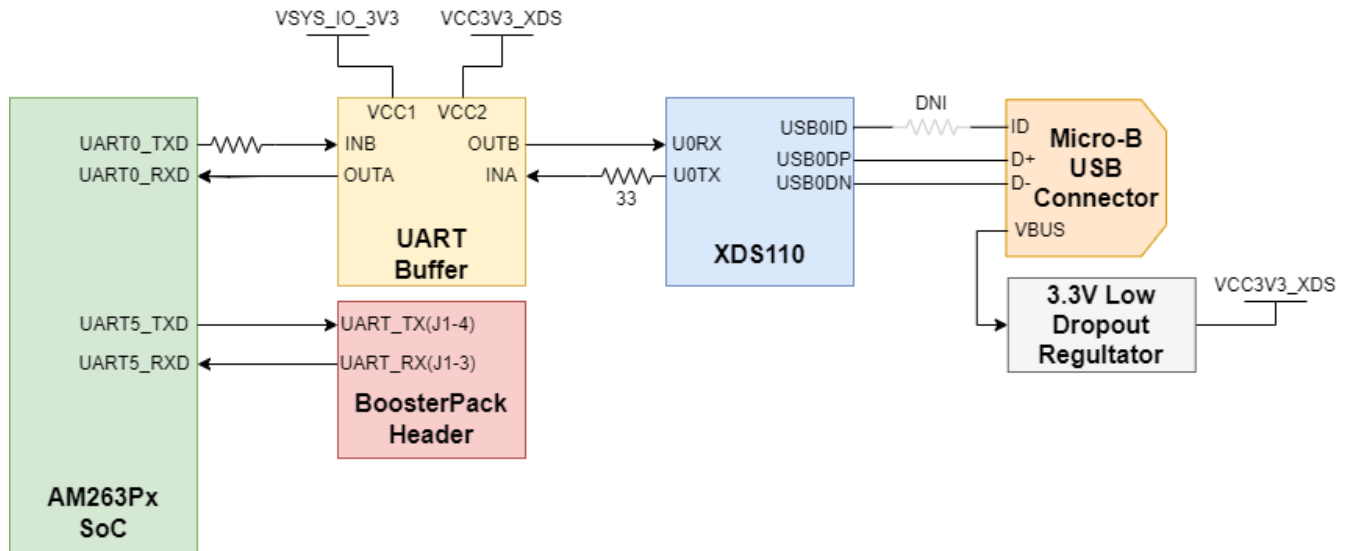
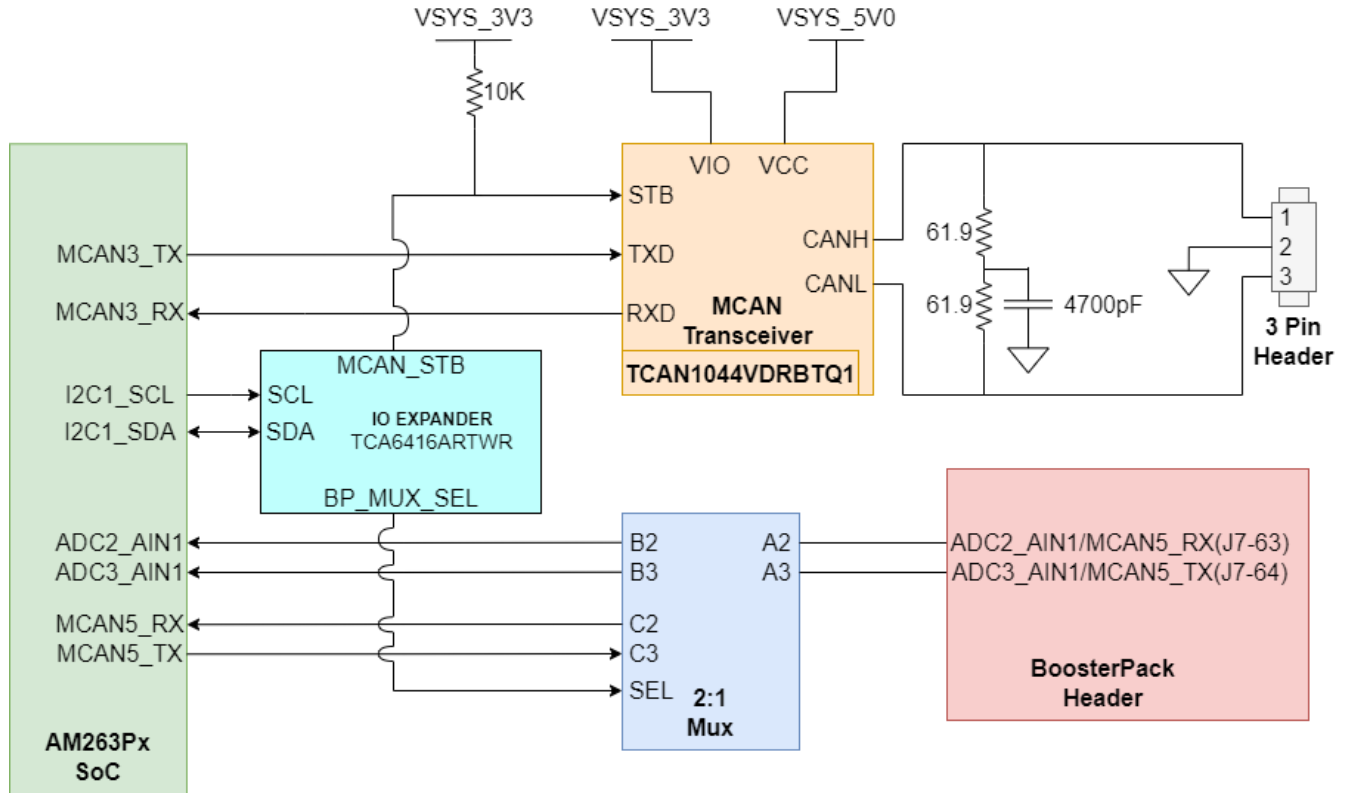


Figure 2-22. UART

## 2.12 MCAN

The LaunchPad is equipped with a single MCAN Transceiver (TCAN1044VDRBTQ1) that is connected to the MCAN3 interface of the AM263Px SoC. The MCAN Transceiver has two power inputs, VIO is the transceiver 3.3V system level shifting supply voltage and VCC is the transceiver 5V supply voltage. The SoC CAN data transmit data input is mapped to TXD of the transceiver and the CAN receive data output of the transceiver is mapped to the MCAN RX signal of the SoC.



**Figure 2-23. MCAN Transceiver and BoosterPack Header**

The system has a 120Ω split termination on the CANH and CANL signals to improve EMI performance. Split termination improves the electromagnetic emissions behavior of the network by eliminating fluctuations in the bus common-mode voltages at the start and end of message transmissions.

The low and high level CAN bus input output lines are terminated to a three pin header.

The standby control signal is an AM263Px SoC GPIO signal. The STB control input has a pullup resistor that is used to have the transceiver be in low-power standby mode to prevent excessive system power. Below is a table that shows the operating modes of the MCAN transceiver based on the STB control input logic.

**Table 2-16. MCAN Transceiver Operating Modes**

STB	Device Mode	Driver	Receiver	RXD Pin
High	Low current standby mode with bus wake-up	Disabled	Low-power receiver and bus monitor enable	High (recessive) until valid WUP is received
Low	Normal Mode	Enabled	Enabled	Mirrors bus state

MCAN5 is routed to the BoosterPack Header via a 2:1 mux. The mux selects whether ADC inputs or MCAN signals are mapped to the BoosterPack Header.

**Table 2-17. MCAN BoosterPack Mux**

BP_MUX_SEL	Condition	Function of Mux
LOW	ADC Inputs Selected	Port A ↔ Port B
HIGH	MCAN TX/RX Selected	Port A ↔ Port C



## 2.13 FSI

The AM263Px LaunchPad supports a fast serial interface by terminating the SoC signals to a 10-pin header. The interface has two lines of data and a clock line for both the receive and transmit signals. The 10-pin header is connected to the 3.3V System voltage supply.

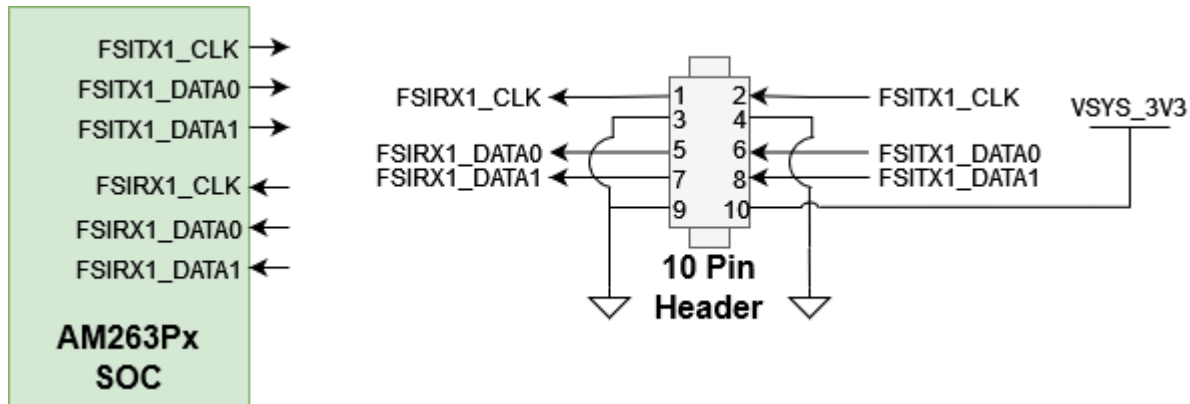


Figure 2-24. FSI 10-Pin Header

## 2.14 JTAG

The AM263Px LaunchPad includes an XDS110 class onboard emulator. The LaunchPad includes all circuitry needed for XDS110 emulation. The emulator uses a USB 2.0 micro-b connector to interface the USB 2.0 signals that are created from the UART-USB bridge. The VBUS power from the connector is used to power the emulator circuit so that the connection to the emulator is not lost when power to the LaunchPad is removed. For more information on the XDS110 and the UART-USB bridge refer to [UART](#)

The XDS110 controls two power status LEDs. For more information on the Power Status LEDs refer to [Power Status LEDs](#)

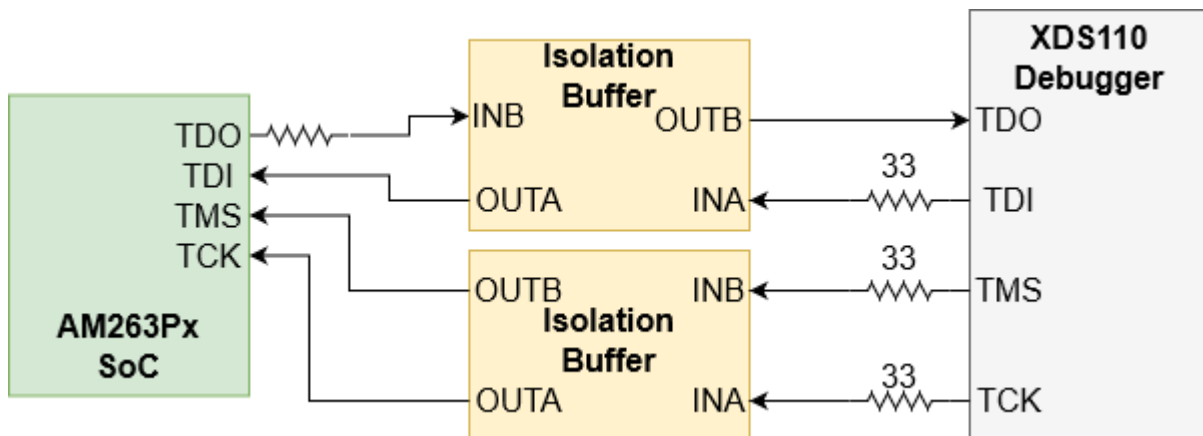


Figure 2-25. JTAG Interface to XDS110

## 2.15 TIVA and Test Automation Header

The board supports two test automation features:

- A USB-based virtual COM port, using the TIVA Test Automation Header.
  - The header allows an external controller to manipulate basic operations such as power down, PORz, warm reset, and boot mode control.
  - The AM263Px SOC I2C instance is connected to the TIVA Test Automation Header - FH12A-402-0.55H.
- A 40 pin test automation header that allows an external controller to manipulate basic operations such as power down, PORz, warm reset, and boot mode control.

- The Test Automation Circuit is powered by a dedicated 3.3V power supply (VSYS\_TA\_3V3) which is generated by a 5V to 3.3V buck regulator (TPS62177DQCR).
- The AM263Px SoC I2C3 instance is connected to both the Test Automation Header and the boot mode IO expander (TCA6408ARGTR).

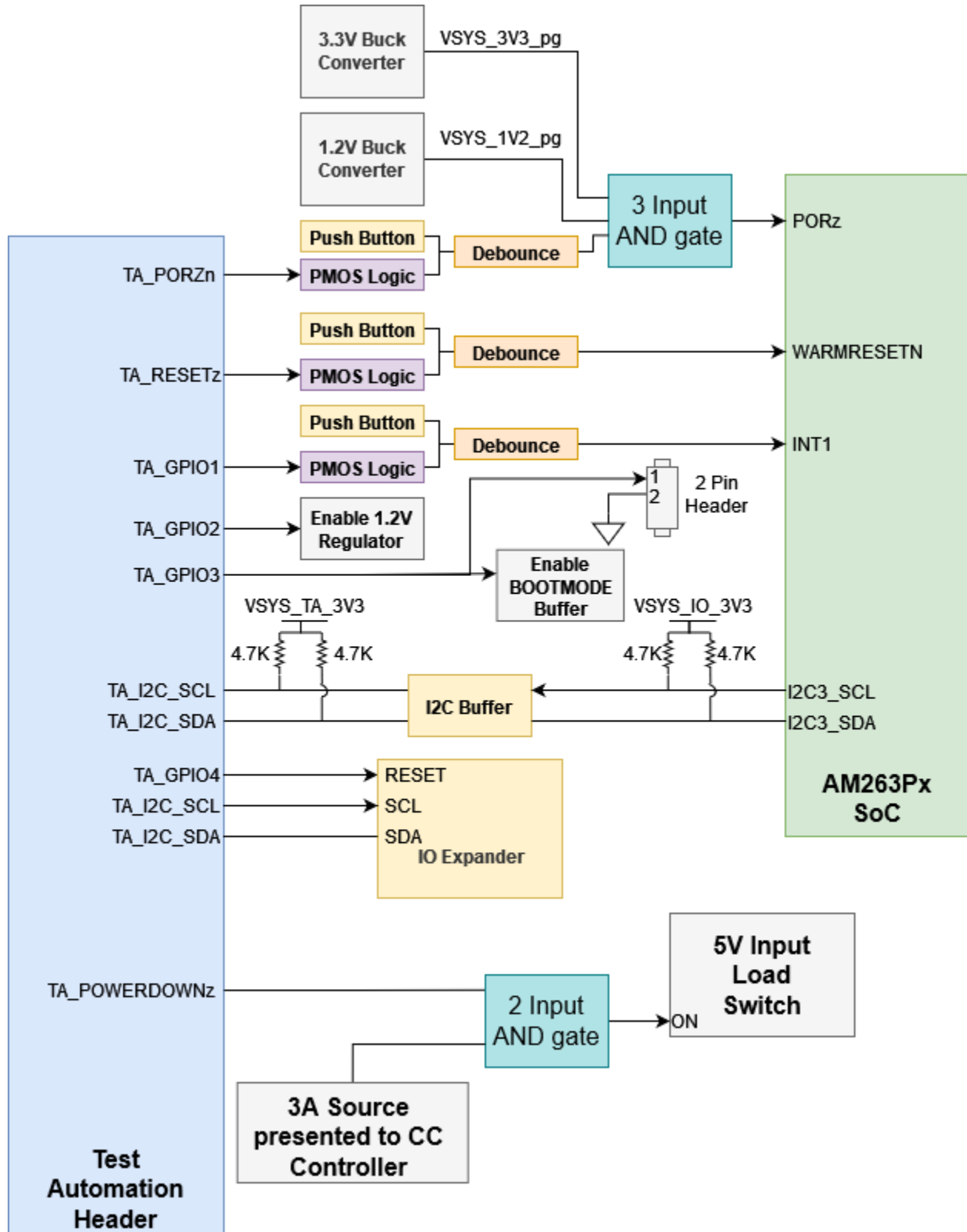


Figure 2-26. Test Automation Header

The following table details the Test Automation mapping.

**Table 2-18. Test Automation GPIO and I2C Mapping**

Signal Name	Description	Direction
TA_POWERDOWNZ	When logic low, disables the 3.3V buck regulator that is used in the first stage of DC/DC conversion	Output
TA_PORZ	When logic low, connects the PORz signal to ground due to PMOS $V_{GS}$ being less than zero creating a power on reset to the MAIN domain	Output
TA_RESEZ	When logic low, connects the WARM RESETn signal to ground due to PMOS $V_{GS}$ being less than zero creating a warm reset to the MAIN domain	Output
TA_GPIO1	When logic low, connects the INTn signal to ground due to PMOS $V_{GS}$ being less than zero creating an interrupt to SoC	Output
TA_GPIO3	When logic low, disables the boot mode buffer output enable	Output
TA_GPIO4	Reset signal for boot mode IO Expander	Output
TA_I2C_SCL	I2C Clock signal used to communicate with bootmode IO expander to change the boot modes.	Output
TA_I2C_SDA	I2C Data signal used to communicate with bootmode IO expander to change the boot modes.	Output

## 2.16 LIN

The AM263Px LaunchPad supports Local Interconnect Network communication with two LIN instances mapped to the BoosterPack header.

### Note

The AM263Px does **not** have an onboard LIN Transceiver

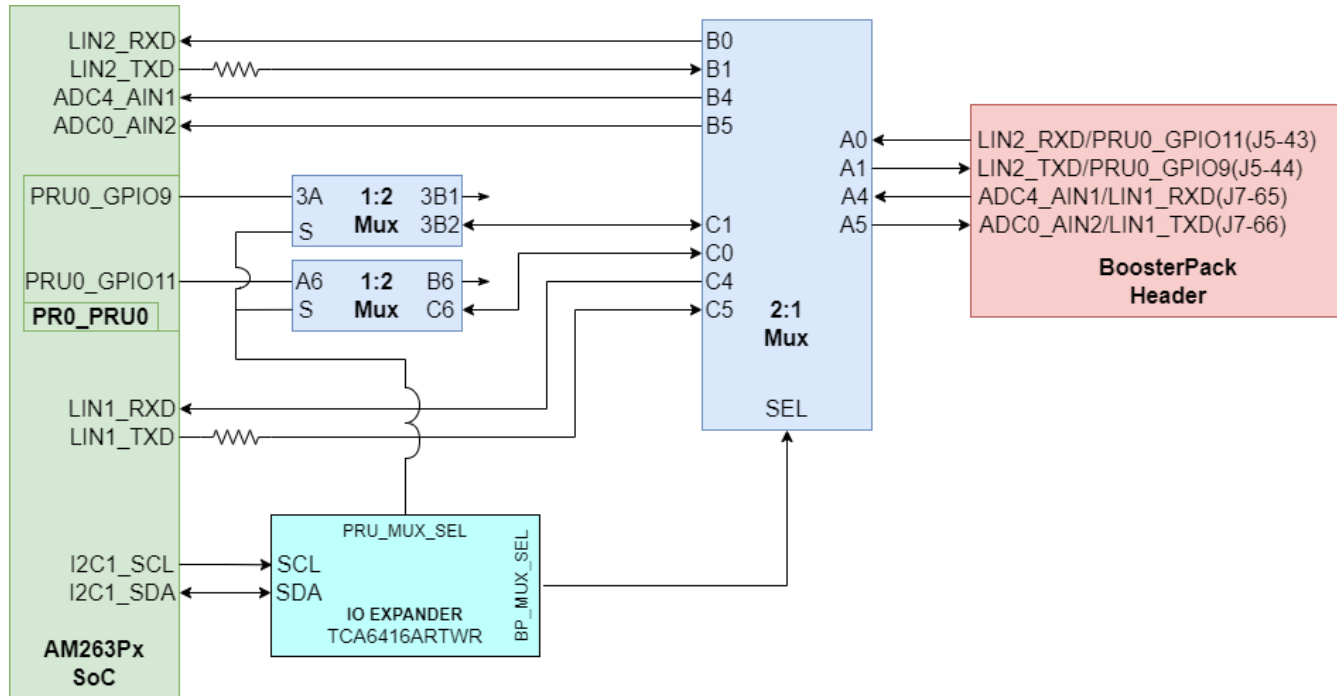


Figure 2-27. LIN Instances to BoosterPack Header

Both LIN instances are mapped to the alternate BoosterPack function 2:1 mux. The alternate BoosterPack function mux also has mappings for ADC inputs and PRU0 GPIO signals.

Table 2-19. LIN 2:1 Mux

PRU_MUX_SEL	BP_MUX_SEL	Function of 2:1 Mux	Signals to BP Header
HIGH	LOW	Port A ↔ Port B	LIN2TX/RX, ADC4_AIN1, ADC0_AIN2
HIGH	HIGH	Port A ↔ Port C	PRU GPIO11/9, LIN1TX/RX
LOW	LOW	Port A ↔ Port B	LIN2TX/RX, ADC4_AIN1, ADC0_AIN2
LOW	HIGH	Port A ↔ Port C	NC, NC, LIN1 TX/RX

## 2.17 ADC and DAC

The AM263Px LaunchPad maps 20 ADC inputs to the BoosterPack header. All of the ADC inputs that are used in the LaunchPad are ESD protected.

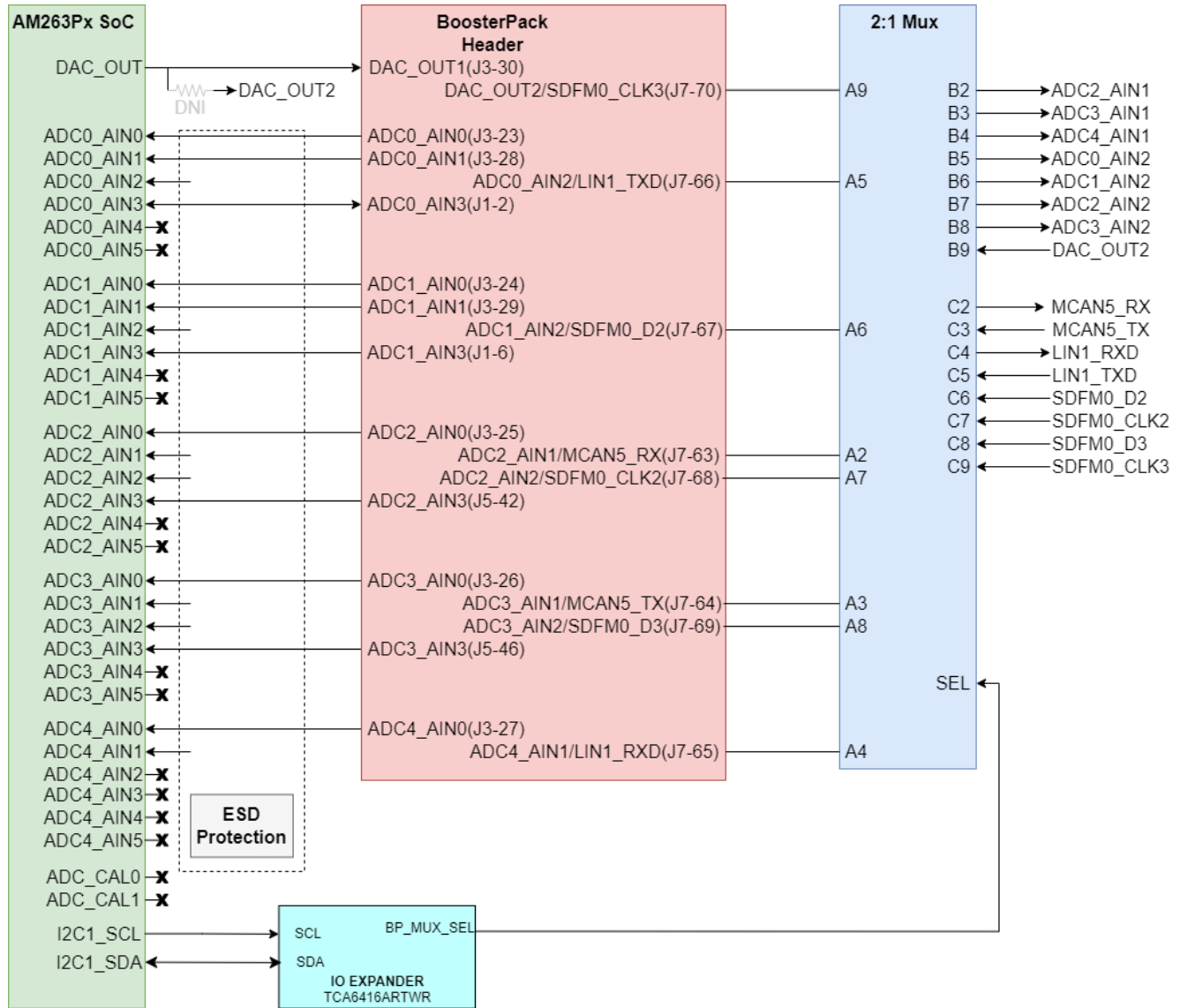


Figure 2-28. ADC/DAC Signal Pathing

Seven of the ADC inputs and one instance of the DAC\_OUT signal is routed to a 2:1 mux (TS3DDR3812RUAR) to offer alternate BoosterPack functionality. The select line of the mux is driven by an AM263Px SoC GPIO signal.

Table 2-20. ADC BoosterPack Mux

BP_MUX_SEL	Condition	Function of Mux
LOW	ADC input/DAC_OUT Selected	Port A ↔ Port B
HIGH	Alternate BP functionality Selected	Port A ↔ Port C

The ADC and DAC require a voltage reference. The AM263Px LaunchPad has two switches that allow the user to switch between the DAC and ADC VREF source.

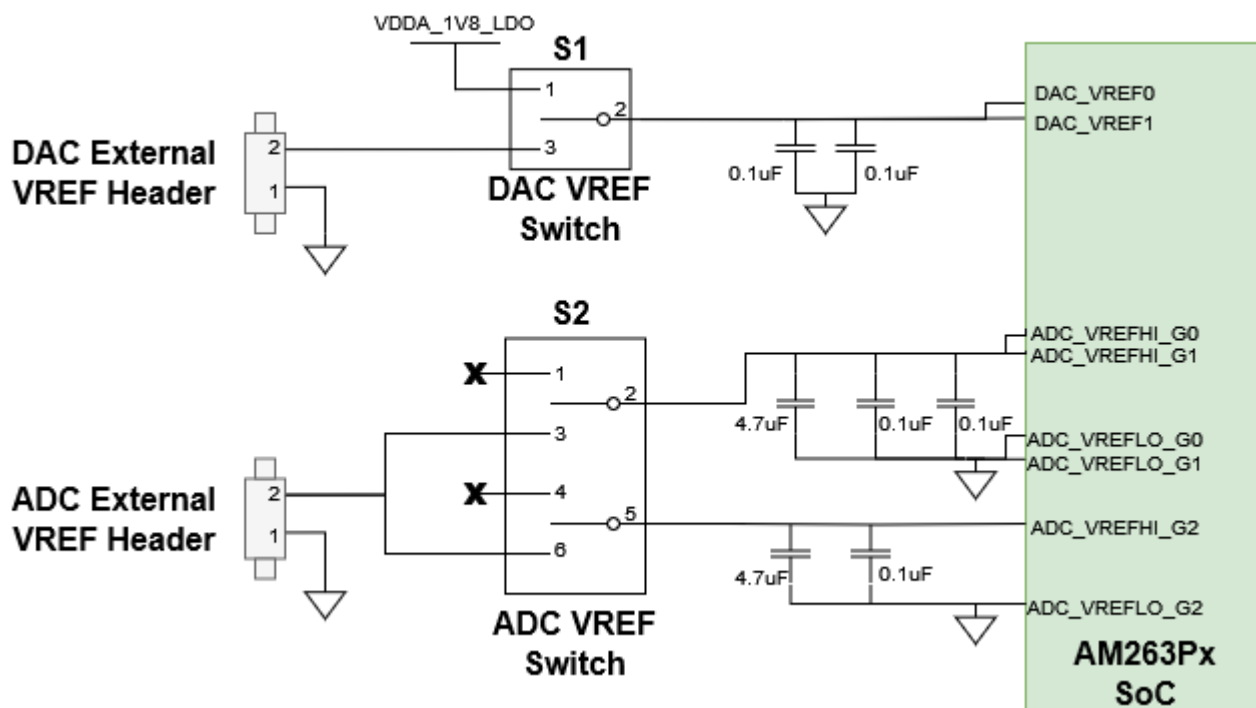


Figure 2-29. ADC and DAC VREF Switches

The DAC VREF Switch (S1) is a single pole double throw switch that controls the input of the ADC VREF inputs of the AM263Px SoC.

Table 2-21. DAC VREF Switch

DAC VREF Switch Position	Reference Selection
Pin 1-2	AM263Px on-die LDO
Pin 2-3	External DAC VREF Header

The ADC VREF Switch (S2) contains two single pole double throw switches that controls the input of the ADC VREF inputs of the AM263Px SoC.

Table 2-22. ADC VREF Switch

ADC VREF Switch Position	Reference Selection
Pin 1-2	OPEN - Allow for reference to be AM263Px on-die LDO reference
Pin 2-3	External ADC VREF Header
Pin 4-5	OPEN - Allow for reference to be AM263Px on-die LDO reference
Pin 5-6	External ADC VREF Header

## 2.18 EQEP and SDFM

The AM263Px LaunchPad internally muxes the eQEP and SDFM signals. The eQEP0 and SDFM1 instances of the AM263Px are terminated to two headers (J24, J15). The eQEP2 and SDFM2 instances of the AM263Px are terminated to two headers (J25, J16).

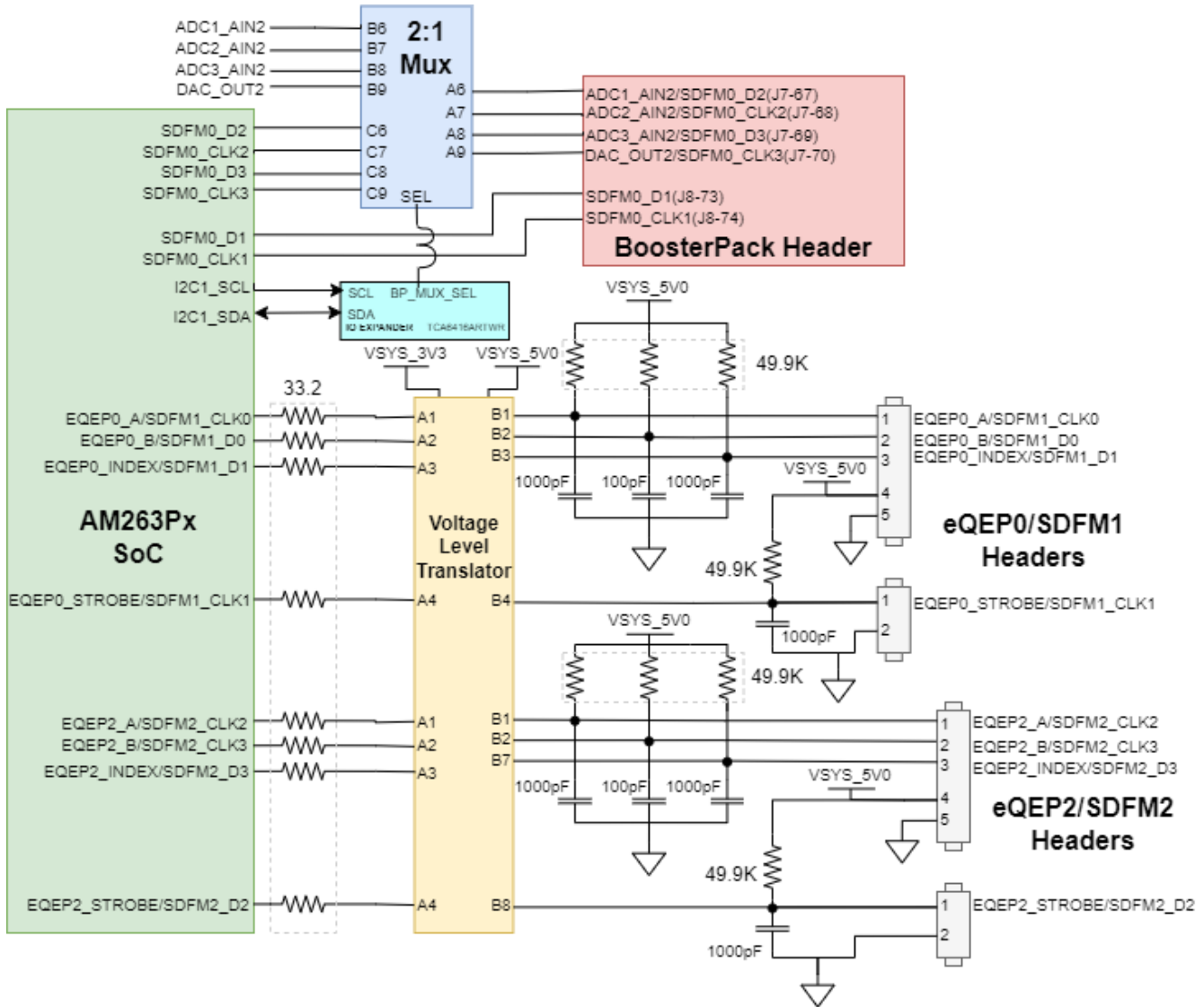


Figure 2-30. EQEP and SDFM Signal Mapping

All eQEP signals have series termination resistors between the AM263Px SoC and the Voltage Level Translator (TXB0108RGYR). The voltage level shifter is responsible for translating the 3.3V to 5V.

SDFM0 is mapped to the BoosterPack Header rather than an independent header. Four of the SDFM0 signals are routed through a 2:1 mux to offer alternate BoosterPack functionality. The select line of the mux is driven by an AM263Px SoC GPIO signal.

Table 2-23. SDFM0 Mux

BP_MUX_SEL	Condition	Function of Mux
LOW	Alternate BP functionality Selected	Port A ↔ Port B
HIGH	SDFM0 Selected	Port A ↔ Port C



## 2.19 EPWM

The AM263Px LaunchPad maps 20 PWM channels (10 PWM\_A/B pairs) to the BoosterPack Header. Each EPWM signal has a series termination resistor. For the mapping of each EPWM signal refer to [Pinmux Mapping](#).

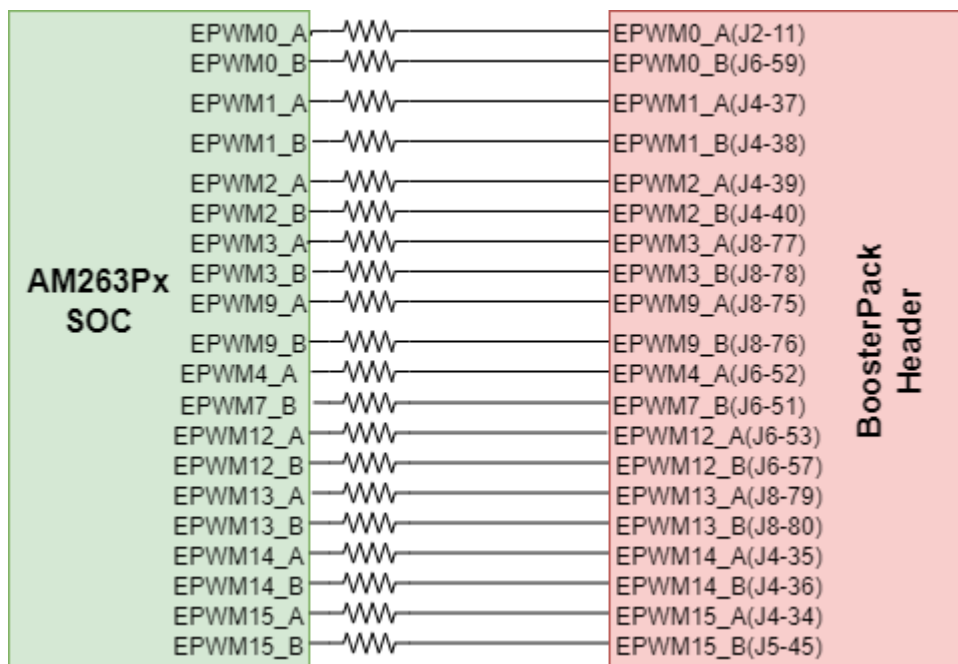


Figure 2-31. EPWM Signal Mapping to BoosterPack Header

## 2.20 BoosterPack Headers

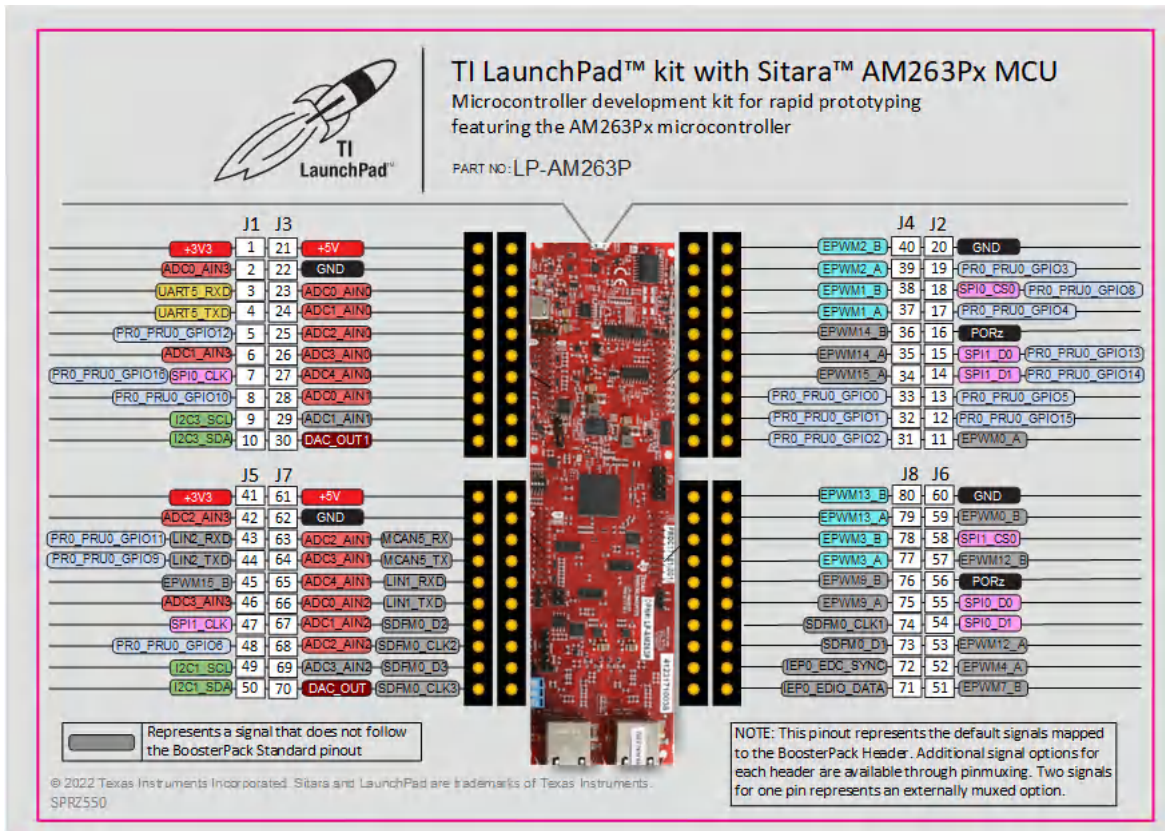


Figure 2-32. AM263Px LaunchPad BoosterPack Pinout

### Note

This pinout represents the default signals mapped to the BoosterPack Header. Additional signal options for each header are available through [Pinmux Mapping](#). Two signals for one pin represents an externally muxed option

The AM263Px LaunchPad supports two fully independent BoosterPack XL connectors. BoosterPack site #1 (J1/J3, J2/J4) is located in between the SoC and the micro-B USB Connector. BoosterPack site #2 (J5/J7, J6/J8) is located in between the SoC and the RJ45 connectors. Each GPIO has multiple functions available through the GPIO mux. The signals connected from the SoC to the BoosterPack headers include:

- Various ADC inputs
- DAC outputs
- UART5
- Various GPIO signals
- SPI0 and SPI1
- I2C1 and I2C3
- Various EPWM channels
- LIN1 and LIN2
- MCAN1
- SDFM0

## 2.21 Pinmux Mapping

The various pinmux options for the BoosterPack connector pins are given below.

**Table 2-24. Pinmux Legend**

Default signal for BP Header	Muxed alternative signal	External MUX for alternate signal options
------------------------------	--------------------------	-------------------------------------------

**Table 2-25. Pinmux Options for J1**

Pin#	Mode0	Mode1	Mode2	Mode3	Mode4	Mode5	Mode6	Mode7	Mode8	Mode9	Mode 10
J1.1	3V3										
J1.2	ADC0_AIN3										
J1.3	EPWM15_B	UART5_RXD	MII1_CRS	MCAN7_TX				GPIO74			EPWM15_B
J1.4	EPWM15_A	UART5_TXD	MII1_COL	MCAN7_RX				GPIO73			EPWM15_A
J1.5	PR0_PRU0_GPIO12		RMII2_TXD1	RGMI2_TD1	MII2_TXD1	EPWM28_B		GPIO100			EPWM28_B
J1.6	ADC1_AIN3										
J1.7	SPI0_CLK	UART3_TXD	LIN3_TXD				FSITX0_CLK	GPIO12			
	PR0_PRU0_GPIO16			RGMI2_TXC	MII2_TXCLK	EPWM27_A		GPIO97			EPWM27_A
J1.8	PR0_PRU0_GPIO10		RMII2_CRS_D V	PR0_UART0_RT Sn	MII2_CRS	EPWM23_A		GPIO89			EPWM22_B
J1.9	EPWM8_B	UART4_RXD	I2C3_SCL	SPI6_D1			FSITX2_D0	GPIO60			EPWM9_B
J1.10	EPWM8_A	UART4_TXD	I2C3_SDA	SPI6_D0			FSITX2_CLK	GPIO59			EPWM8_A

**Table 2-26. Pinmux Options for J2**

Pin#	Mode0	Mode1	Mode2	Mode3	Mode4	Mode5	Mode6	Mode7	Mode8	Mode9	Mode10
J2.11	EPWM0_A							GPIO43			EPWM0_A
J2.12	PR0_PRU0_GPIO15		RMII2_TX_EN	RGMI2_TX_C TL	MII2_TX_EN	EPWM27_B		GPIO98			
J2.13	PR0_PRU0_GPIO5		RMII2_RX_ER		MII2_RX_ER	EPWM22_A		GPIO87			EPWM22_A
J2.14	SPI1_D1	UART5_RXD				XBAROUT4	FSIRX0_D1	GPIO18			
	PR0_PRU0_GPIO14 <sup>A</sup>			RGMI2_TD3 <sup>A</sup>	MII2_TXD3 <sup>A</sup>	EPWM29_B <sup>A</sup>		GPIO102 <sup>A</sup>			EPWM27_B <sup>A</sup>
J2.15	SPI1_D0	UART5_TXD				XBAROUT3	FSIRX0_D0	GPIO17			
	PR0_PRU0_GPIO13 <sup>A</sup>			RGMI2_TD2 <sup>A</sup>	MII2_TXD2 <sup>A</sup>	EPWM29_A <sup>A</sup>		GPIO101 <sup>A</sup>			EPWM27_B <sup>A</sup>
J2.16	PORz										
J2.17	PR0_PRU0_GPIO4			RGMI2_RX_C TL	MII2_RXDV	EPWM24_B		GPIO92			EPWM24_B
J2.18	SPI0_CS0	UART3_RXD	LIN3_RXD					GPIO11			
	PR0_PRU0_GPIO8					EPWM23_B		GPIO90			EPWM29_A
J2.19	PR0_PRU0_GPIO3			RGMI2_RD3	MII2_RXD3	EPWM26_B		GPIO96			EPWM26_B
J2.20	GND										

<sup>A</sup> - Applies to revision A of LP-AM263P board only.

**Table 2-27. Pinmux Options for J3**

Pin#	Mode0	Mode1	Mode2	Mode3	Mode4	Mode5	Mode6	Mode7	Mode8	Mode9
J3.21	5V									
J3.22	GND									
J3.23	ADC0_AIN0									
J3.24	ADC1_AIN0									
J3.25	ADC2_AIN0									
J3.26	ADC3_AIN0									
J3.27	ADC4_AIN0									
J3.28	ADC0_AIN1									
J3.29	ADC1_AIN1									
J3.30	DAC_OUT1									

**Table 2-28. Pinmux Options for J4**

Pin#	Mode0	Mode1	Mode2	Mode3	Mode4	Mode5	Mode6	Mode7	Mode8	Mode9	Mode10
J4.31	PR0_PRU0_GPIO2			RGMII2_RD2	MII2_RXD2	EPWM26_A		GPIO95			EPWM26_A
J4.32	PR0_PRU0_GPIO1		RMII2_RXD1	RGMII2_RD1	MII2_RXD1	EPWM25_B		GPIO94			EPWM25_B
J4.33	PR0_PRU0_GPIO0		RMII2_RXD0	RGMII2_RD0	MII2_RXD0	EPWM25_A		GPIO93			EPWM25_A
J4.34	EPWM15_A	UART5_TXD	MII1_COL	MCAN7_RX				GPIO73			EPWM15_A
J4.35	EPWM14_A	UART1_DSRn	SPI7_D1	MCAN6_RX				GPIO71			EPWM14_A
J4.36	EPWM14_B		MII1_RX_ER					GPIO72			EPWM14_B
J4.37	EPWM1_A							GPIO45			EPWM1_A
J4.38	EPWM1_B							GPIO46			EPWM1_B
J4.39	EPWM2_A							GPIO47			EPWM2_A
J4.40	EPWM2_B							GPIO48			EPWM2_B

**Table 2-29. Pinmux Options for J5**

Pin#	Mode0	Mode1	Mode2	Mode3	Mode4	Mode5	Mode6	Mode7	Mode8	Mode9	Mode10
J5.41	3V3										
J5.42	ADC2_AIN3										
J5.43	LIN2_RXD	UART2_RXD	SPI2_D0					GPIO21			
	PR0_PRU0_GPIO11		RMII2_TXD0	RGMII2_TD0	MII2_TXD0	EPWM28_A		GPIO99			EPWM28_A
J5.44	LIN2_TXD	UART2_TXD	SPI2_D1					GPIO22			
	PR0_PRU0_GPIO9			PR0_UART0_CTSn	MII2_COL	EPWM22_B		GPIO88			
J5.45	EPWM15_B	UART5_RXD	MII1_CRS	MCAN7_TX				GPIO74			EPWM15_B
J5.46	ADC3_AIN3										
J5.47	SP1_CLK	UART4_RXD	LIN4_RXD			XBAROUT2	FSIRX0_CLK	GPIO16			
J5.48	PR0_PRU0_GPIO6		RMII2_REF_CLK	RGMII2_RXC	MII2_RXCLK	EPWM24_A		GPIO91			EPWM24_A
J5.49	I2C1_SCL		SPI3_CS0			XBAROUT7		GPIO23			

**Table 2-29. Pinmux Options for J5 (continued)**

Pin#	Mode0	Mode1	Mode2	Mode3	Mode4	Mode5	Mode6	Mode7	Mode8	Mode9	Mode10
J5.50	I2C1_SDA		SPI3_CLK			XBAROUT8		GPIO24			

**Table 2-30. Pinmux Options for J6**

Pin#	Mode0	Mode1	Mode2	Mode3	Mode4	Mode5	Mode6	Mode7	Mode8	Mode9	Mode10
J6.51	EPWM7_B			SPI6_CLK				GPIO58			EPWM5_B
J6.52	EPWM4_A							GPIO51			EPWM4_A
J6.53	EPWM12_A	UART3_CTSn	SPI4_CS1		MCAN7_RX		OSPI_D5	GPIO67			EPWM12_A
J6.54	SPI0_D1						FSITX0_D1	GPIO14			
	PR0_PRU0_GPIO14 <sup>E2A</sup>			RGMII2_TD3 <sup>E2A</sup>	MII2_TXD3 <sup>E2A</sup>	EPWM29_B <sup>E2A</sup>		GPIO102 <sup>E2A</sup>			EPWM29_B <sup>E2A</sup>
J6.55	SPI0_D0						FSITX0_D0	GPIO13			
	PR0_PRU0_GPIO13 <sup>E2A</sup>			RGMII2_TD2 <sup>E2A</sup>	MII2_TXD2 <sup>E2A</sup>	EPWM29_A <sup>E2A</sup>		GPIO101 <sup>E2A</sup>			EPWM27_B <sup>E2A</sup>
J6.56	PORz										
J6.57	EPWM12_B	UART1_DCDn	SPI7_CS0		MCAN7_TX		OSPI_D7	GPIO68			EPWM10_A
J6.58	SPI1_CS0	UART4_TXD	LIN4_TXD			XBAROUT1		GPIO15			
J6.59	EPWM0_B							GPIO44			EPWM0_B
J6.60	GND										

E2A - Applies to revision E2A of LP-AM263P board only.

**Table 2-31. Pinmux Options for J7**

Pin#	Mode0	Mode1	Mode2	Mode3	Mode4	Mode5	Mode6	Mode7	Mode8	Mode9
J7.61	5V									
J7.62	GND									
J7.63	ADC2_AIN1									
	PR0_PRU1_GPIO16	MCAN5_RX		FSITX3_CLK	TRC_DATA10			GPIO113		
J7.64	ADC3_AIN1									
	PR0_PRU1_GPIO15	MCAN5_TX		FSITX3_D0	TRC_DATA11			GPIO114		
J7.65	ADC4_AIN1									
	LIN1_RXD	UART1_RXD	SPI2_CS0	OSPI_ECC_FAIL		XBAROUT5		GPIO19	OSPI_RESET_OUT1	
J7.66	ADC0_AIN2									
	LIN1_TXD	UART1_TXD	SPI2_CLK	OSPI_RESET_OUT0		XBAROUT6		GPIO20		
J7.67	ADC1_AIN2									
	UART5_RXD							GPIO127	SDFM0_D2	CHANNEL0
J7.68	ADC2_AIN2									
	UART5_TXD					I2C3_SCL		GPIO126	SDFM0_CLK2	CHANNEL8

**Table 2-31. Pinmux Options for J7 (continued)**

Pin#	Mode0	Mode1	Mode2	Mode3	Mode4	Mode5	Mode6	Mode7	Mode8	Mode9
J7.69	ADC3_AIN2									
	MCAN3_RX							GPIO129	SDFM0_D3	CHANNEL1
J7.70	DAC_OUT									
	MCAN3_TX	UART5_RXD						GPIO128	SDFM0_CLK3	CHANNEL9

**Table 2-32. Pinmux Options for J8**

Pin#	Mode0	Mode1	Mode2	Mode3	Mode4	Mode5	Mode6	Mode7	Mode8	Mode9	Mode10
J8.71	PR0_PRU1_GPIO 18		UART3_T XD	PR0_IEP0_EDIO_DAT A_IN_OUT31	TRC_CTL	XBAROUT1 4		GPIO120			EQEP1_B
J8.72	PR0_PRU1_GPIO 19		UART3_R XD	PR0_IEP0_EDC_SYN C_OUT0	TRC_CLK	XBAROUT1 3		GPIO119			EQEP1_A
J8.73	PR0_PRU1_GPIO 17		UART5_C TSn	PR0_IEP0_EDIO_DAT A_IN_OUT30				GPIO125	SDFM0_D1		
J8.74	PR0_PRU1_GPIO 7	CPTS0_TS_SYN C	UART5_R TSn	PR0_IEP0_EDC_SYN C_OUT1		I2C3_SDA		GPIO124	SDFM0_CLK1		
J8.75	EPWM9_A			SPI7_CS0	MCAN4_R X		FSITX2_DATA 1	GPIO61			EPWM9_A
J8.76	EPWM9_B	UART1_RTSn		SPI7_CLK	MCAN4_T X		FSIRX2_CLK	GPIO62			EPWM11_B
J8.77	EPWM3_A							GPIO49			EPWM3_A
J8.78	EPWM3_B							GPIO50			EPWM6_A
J8.79	EPWM13_A	UART1_RIn	SPI7_CLK				OSPL_D3	GPIO69			EPWM13_A
J8.80	EPWM13_B	UART1_DTRn	SPI7_D0				OSPL_ECC_FA IL	GPIO70			EPWM13_B

**Table 2-33. Pinmux Legend**

Default signal for BP Header	Muxed alternative signal	External MUX for alternate signal options
------------------------------	--------------------------	-------------------------------------------

## **3 Hardware Design Files**

### **3.1 Schematics**

### **3.2 PCB Layouts**

### **3.3 Bill of Materials (BOM)**



## 4 Compliance Information

### 4.1 Compliance and Certifications

All components selected meet RoHS compliance.

## 5 Additional Information

### Trademarks

LaunchPad™, Texas Instruments™, and Sitara™ are trademarks of Texas Instruments. All trademarks are the property of their respective owners.

### 5.1 Sitara MCU+ Academy

TI offers the [MCU+ Academy](#) as a resource for designing with the MCU+ software and tools on supported devices. The MCU+ Academy features easy-to-use training modules that range from the basics of getting started to advanced development topics.

### 5.2 Hardware Changes from RevE2 to RevA

The below are the changes done from Revision-E2 of LP-AM263P to Revision-A of LP-AM263P

1. The Boosterpack pins have been updated such that the pins PR0\_PRU0\_GPIO13 and PR0\_PRU0\_GPIO14 which were muxed on Boosterpack pins J6.54 and J6.55 are now muxed onto pins J2.14 and J2.15 pins. This is made to match the [BOOSTXL-IOLINKM-8](#) Boosterpack requirements. Please note that here the alternate function can be selected based on different Muxes and their respective individual controls.
2. The OSPI0 flash footprint has been made compatible with a standard OSPI PSRAM part footprint. Now a PSRAM part can also be mounted onto the U7(OSPI0 flash) footprint for evaluation. The resistor R443 must be mounted and R444 must be made DNI for evaluating an OSPI PSRAM part. Please refer LP-AM263P RevA schematics for more details.

### 5.3 Known Board Changes/Issues

The below sections capture all the known issues/observations on the board and solutions/fixes for the same. Please note that some of these are already fixed on boards ordered from ti.com, as mentioned in respective sections.

#### 5.3.1 OSPI DQS and LBCLK nets swap

This change/issue applies to only Revision E2A(PROC171E2) of LP-AM263P board.

In AM263P the ball pins for OSPI DQS and LBCLK are as per below

- OSPI0\_DQS is from Ball pin M3
- OSPI0\_LBCLKO is from Ball pin L3

But as seen in the below image from LP-AM263P Schematics, the nets are wrongly swapped.

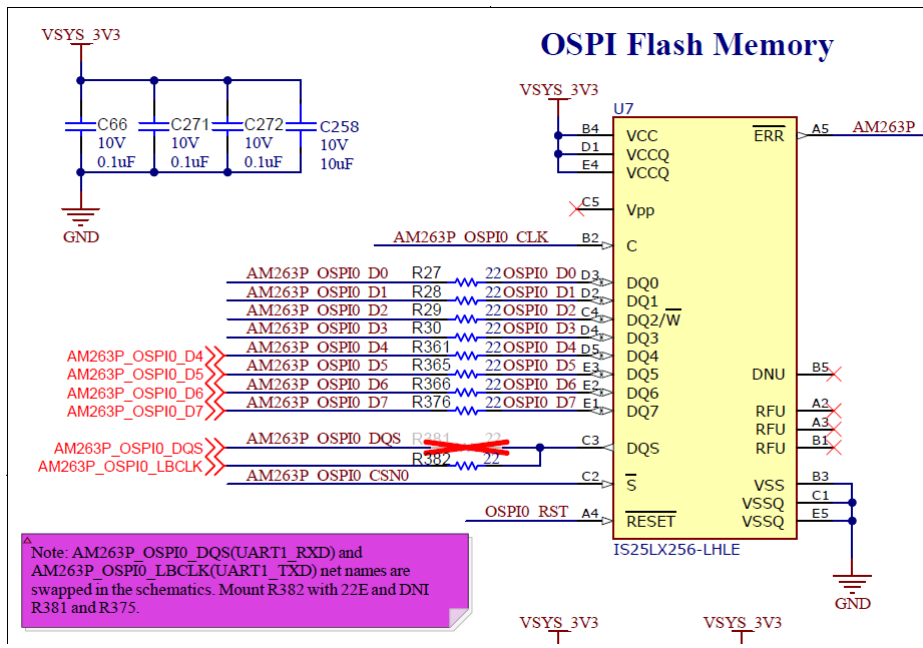


Figure 5-1. OSPI DQS and LBCLK nets caution note in LP-AM263P Schematic

Hence to rectify this, as mentioned in the same schematic the resistor R381 is unmounted and the resistor R382 is mounted with 22Ω resistor. Also the resistor R375 is unmounted.

All boards ordered from ti.com already have this change made.

### 5.3.2 XDS110 Debugger Bricking Issue

It has been found that few EVMs when connected to the PC and connect through Code Composer Studio(CCS), the user is prompted to update the firmware as per below window. Upon clicking on Update button, the update is unsuccessful and CCS just disconnects from the board and the board is no longer detected by CCS. This has been mostly observed with CCS versions 12.4 and above.

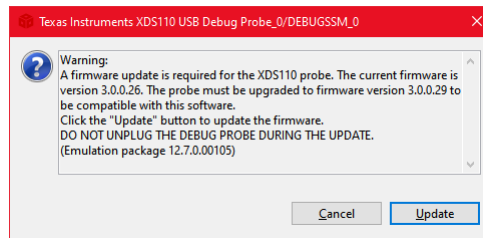
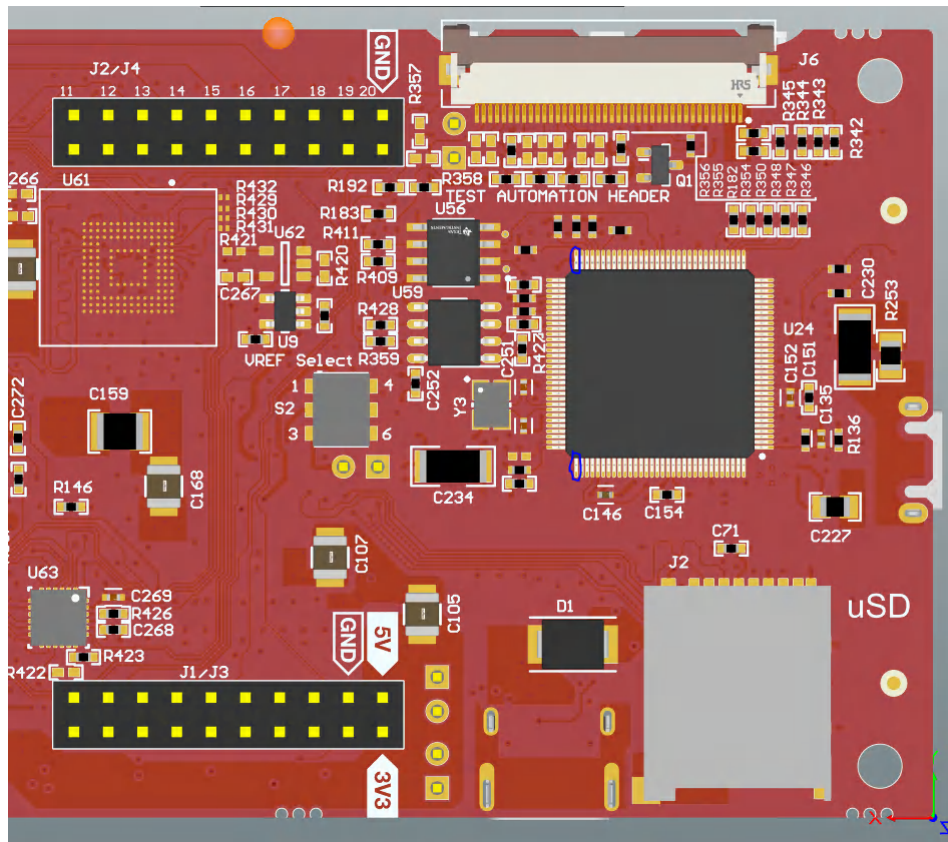


Figure 5-2. CCS prompt to update firmware

The below are the steps of recovering a board when CCS fails to detect the board as mentioned above.

The failure to detect the board is mostly attributed to the wrong firmware version on the XDS110 debugger on the board. Thus the XDS110 debugger would need to be re-flashed with the latest firmware available with the CCS on the user's PC. Follow the below steps to do the same.

1. Disconnect all cables connected to LP-AM263P.
2. Short pins 64 and 97(shown in below image) of the U24 component(TM4C being the XDS110 debugger) and connect back the USB Micro-B debugger cable to LP-AM263P and PC, while pins 64 and 97 are shorted. Now the XDS110 debugger will be in DFU mode.



**Figure 5-3. Location of Pins 64 and 97 on U24**

3. Open Command Prompt on your Windows PC and navigate to `C:\ti\ccs12XX\ccs\ccs_base\common\uscif\xds110`, where 12XX corresponds to the CCS version on the PC.
4. Run command `"xdsdfu -e"` and the device must be reported with Mode as "DFU". If not, please repeat Steps 1 to 3 ensuring the pin shorting is done properly.
5. After the debugger is in DFU mode, run command `"xdsdfu -f firmware_3.0.0.XX.bin -r"` where 3.0.0.XX is the corresponding XDS firmware version found in "`C:\ti\ccs12XX\ccs\ccs_base\common\uscif\xds110`" path. This starts the firmware upgrade utility and flashes the mentioned firmware to the XDS110 debugger.
6. Once step 5 is complete, run command `"xdsdfu -e"` once more to see that the XDS110 debugger is detected by the PC as shown in below image with all the above steps.

```

Command Prompt
C:\ti\ccs1270\ccs\ccs_base\common\uscif\xds110>xdsdfu -e
USB Device Firmware Upgrade Utility
Copyright (c) 2008-2019 Texas Instruments Incorporated. All rights reserved.
Scanning USB buses for supported XDS110 devices...

<<<< Device 0 >>>>
VID: 0x1cbe   PID: 0x00ff
Device Name:  Tiva Device Firmware Update
Manufacturer: Texas Instruments Incorporated
Serial Num:   00000000
Mode:         DFU
Found 1 device.
C:\ti\ccs1270\ccs\ccs_base\common\uscif\xds110>xdsdfu -f firmware_3.0.0.29.bin -r
USB Device Firmware Upgrade Utility
Copyright (c) 2008-2019 Texas Instruments Incorporated. All rights reserved.
Scanning USB buses for supported XDS110 devices...
Downloading firmware_3.0.0.29.bin to device...
C:\ti\ccs1270\ccs\ccs_base\common\uscif\xds110>xdsdfu -e
USB Device Firmware Upgrade Utility
Copyright (c) 2008-2019 Texas Instruments Incorporated. All rights reserved.
Scanning USB buses for supported XDS110 devices...

<<<< Device 0 >>>>
VID: 0x0451   PID: 0xbef3
Device Name:  XDS110 Embed with CMSIS-DAP
Version:      3.0.0.29
Manufacturer: Texas Instruments
Serial Num:   SDE00280
Mode:         Runtime
Configuration: Standard
Found 1 device.
C:\ti\ccs1270\ccs\ccs_base\common\uscif\xds110>_
  
```

**Figure 5-4. XDS110 Firmware update commands in Command Prompt**

Post the above steps are complete, CCS should be able to detect and connect to the XDS110 debugger on LP-AM263P.

More details about XDS110 firmware and updating it can be found in [https://software-dl.ti.com/ccs/esd/documents/xdsdebugprobes/emu\\_xds110.html#manual-update](https://software-dl.ti.com/ccs/esd/documents/xdsdebugprobes/emu_xds110.html#manual-update)

### 5.3.3 eMMC CMD and CLK nets swap

This change/issue applies to both Revision E2A(PROC171E2) and Revision A(PROC171A) of the LP-AM263P board.

The LP-AM263P has an eMMC footprint on board, for the part MTFC8GAMALBH-AAT. But it is seen that the CMD and CLK nets are wrongly swapped. The correct nets should be connected as per below

- U61 Pin M6 should be connected to AM263P\_EMMC0\_CLK\_MUX net
- U61 Pin M5 should be connected to AM263P\_EMMC0\_CMD\_MUX net

Users are suggested to do board re-work before using this eMMC footprint. Please raise an e2e ticket for details on this.

## 6 Related Documentation

### 6.1 Supplemental Content

This LaunchPad uses various other TI components for its functions. A consolidated list of these components with links to their TI data sheets is shown below:

- [TUSB320USB Type-C Configuration Channel Logic and Port Controller](#)
- [TPD4E02B04 4-Channel ESD Protection Diode for USB Type-C](#)
- [TPS22965x-Q1 5.5-V, 4-A, 16-mΩ On-Resistance Load Switch](#)
- [TPS6291x 3-V to 17-V, 2-A/3-A Low Noise and Low Ripple Buck Converter](#)
- [TPS748 1.5-A Low-Dropout Linear Regulator](#)
- [TCA6408A Low-Voltage 8-Bit I<sup>2</sup>C and SMBus I/O Expander](#)
- [SN74AVC4T245 Dual-Bit Bus Transceiver with Configurable Voltage Translation](#)
- [TPS22918-Q1, 5.5-V, 2-A, 52-mΩ On-Resistance Load Switch](#)
- [TPD6E001 Low-Capacitance 6-Channel ESD-Protection for High-Speed Data Interfaces](#)
- [XDS110 JTAG Debug Probe](#)
- [TS5A23159 1-Ω 2-Channel SPDT Analog Switch](#)
- [TCAN1044V-Q1 Automotive Fault-Protected CAN FD Transceiver](#)
- [DP83869HM High Immunity 10/100/1000 Ethernet Physical Layer Transceiver](#)
- [TS3DDR3812 12-Channel, 1:2 MUX/DEMUX Switch for DDR3 Applications](#)
- [TCA9617B Level-Translating I<sup>2</sup>C Bus Repeater](#)
- [SN74CB3Q3257 4-Bit 1-of-2 FET Multiplexer/Demultiplexer](#)
- [TPIC2810 8-Bit LED Driver with I<sup>2</sup>C Interface](#)
- [TPS796xx 1-A Low-Dropout Linear Regulators](#)
- [TXB0108 8-Bit Bidirectional Voltage-Level Translator with Auto-Direction Sensing](#)
- [TCA6416ARTWR 16-bit translating 1.65- to 5.5-V I<sup>2</sup>C/SMBus I/O expander](#)

## 7 References

In addition to this document, the following references are available for download at [www.ti.com](http://www.ti.com).

- [AM263P4 Sitara™ Microcontrollers](#)
- [AM263Px Sitara™ Microcontrollers Data Sheet](#)
- [AM263Px Sitara™ Microcontrollers Technical Reference Manual](#)
- [AM263Px Sitara™ Microcontrollers Silicon Errata](#)
- [Texas Instruments Code Composer Studio](#)
- [Updating XDS110 Firmware](#)
  - To find the serial number, only follow steps 1 and 2 of updating XDS110 firmware

## 8 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

### Changes from September 30, 2024 to January 31, 2026 (from Revision A (September 2024) to Revision B (January 2026))

	Page
• Updated the SPI diagram for new RevA LP-AM263P board.....	32
• Updated changes for RevA of LP-AM263P.....	45
• Initial creation to capture details of changes for RevA of LP-AM263P.....	50

## STANDARD TERMS FOR EVALUATION MODULES

1. *Delivery:* TI delivers TI evaluation boards, kits, or modules, including any accompanying demonstration software, components, and/or documentation which may be provided together or separately (collectively, an "EVM" or "EVMs") to the User ("User") in accordance with the terms set forth herein. User's acceptance of the EVM is expressly subject to the following terms.
  - 1.1 EVMs are intended solely for product or software developers for use in a research and development setting to facilitate feasibility evaluation, experimentation, or scientific analysis of TI semiconductors products. EVMs have no direct function and are not finished products. EVMs shall not be directly or indirectly assembled as a part or subassembly in any finished product. For clarification, any software or software tools provided with the EVM ("Software") shall not be subject to the terms and conditions set forth herein but rather shall be subject to the applicable terms that accompany such Software
  - 1.2 EVMs are not intended for consumer or household use. EVMs may not be sold, sublicensed, leased, rented, loaned, assigned, or otherwise distributed for commercial purposes by Users, in whole or in part, or used in any finished product or production system.
2. *Limited Warranty and Related Remedies/Disclaimers:*
  - 2.1 These terms do not apply to Software. The warranty, if any, for Software is covered in the applicable Software License Agreement.
  - 2.2 TI warrants that the TI EVM will conform to TI's published specifications for ninety (90) days after the date TI delivers such EVM to User. Notwithstanding the foregoing, TI shall not be liable for a nonconforming EVM if (a) the nonconformity was caused by neglect, misuse or mistreatment by an entity other than TI, including improper installation or testing, or for any EVMs that have been altered or modified in any way by an entity other than TI, (b) the nonconformity resulted from User's design, specifications or instructions for such EVMs or improper system design, or (c) User has not paid on time. Testing and other quality control techniques are used to the extent TI deems necessary. TI does not test all parameters of each EVM. User's claims against TI under this Section 2 are void if User fails to notify TI of any apparent defects in the EVMs within ten (10) business days after delivery, or of any hidden defects with ten (10) business days after the defect has been detected.
  - 2.3 TI's sole liability shall be at its option to repair or replace EVMs that fail to conform to the warranty set forth above, or credit User's account for such EVM. TI's liability under this warranty shall be limited to EVMs that are returned during the warranty period to the address designated by TI and that are determined by TI not to conform to such warranty. If TI elects to repair or replace such EVM, TI shall have a reasonable time to repair such EVM or provide replacements. Repaired EVMs shall be warranted for the remainder of the original warranty period. Replaced EVMs shall be warranted for a new full ninety (90) day warranty period.

### **WARNING**

**Evaluation Kits are intended solely for use by technically qualified, professional electronics experts who are familiar with the dangers and application risks associated with handling electrical mechanical components, systems, and subsystems.**

**User shall operate the Evaluation Kit within TI's recommended guidelines and any applicable legal or environmental requirements as well as reasonable and customary safeguards. Failure to set up and/or operate the Evaluation Kit within TI's recommended guidelines may result in personal injury or death or property damage. Proper set up entails following TI's instructions for electrical ratings of interface circuits such as input, output and electrical loads.**

**NOTE:**

**EXPOSURE TO ELECTROSTATIC DISCHARGE (ESD) MAY CAUSE DEGRADATION OR FAILURE OF THE EVALUATION KIT; TI RECOMMENDS STORAGE OF THE EVALUATION KIT IN A PROTECTIVE ESD BAG.**

### 3 Regulatory Notices:

#### 3.1 United States

##### 3.1.1 Notice applicable to EVMs not FCC-Approved:

**FCC NOTICE:** This kit is designed to allow product developers to evaluate electronic components, circuitry, or software associated with the kit to determine whether to incorporate such items in a finished product and software developers to write software applications for use with the end product. This kit is not a finished product and when assembled may not be resold or otherwise marketed unless all required FCC equipment authorizations are first obtained. Operation is subject to the condition that this product not cause harmful interference to licensed radio stations and that this product accept harmful interference. Unless the assembled kit is designed to operate under part 15, part 18 or part 95 of this chapter, the operator of the kit must operate under the authority of an FCC license holder or must secure an experimental authorization under part 5 of this chapter.

##### 3.1.2 For EVMs annotated as FCC – FEDERAL COMMUNICATIONS COMMISSION Part 15 Compliant:

#### **CAUTION**

This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

#### **FCC Interference Statement for Class A EVM devices**

*NOTE: This equipment has been tested and found to comply with the limits for a Class A digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference when the equipment is operated in a commercial environment. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instruction manual, may cause harmful interference to radio communications. Operation of this equipment in a residential area is likely to cause harmful interference in which case the user will be required to correct the interference at his own expense.*

#### **FCC Interference Statement for Class B EVM devices**

*NOTE: This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:*

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

#### 3.2 Canada

##### 3.2.1 For EVMs issued with an Industry Canada Certificate of Conformance to RSS-210 or RSS-247

#### **Concerning EVMs Including Radio Transmitters:**

This device complies with Industry Canada license-exempt RSSs. Operation is subject to the following two conditions:

(1) this device may not cause interference, and (2) this device must accept any interference, including interference that may cause undesired operation of the device.

#### **Concernant les EVMs avec appareils radio:**

Le présent appareil est conforme aux CNR d'Industrie Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes: (1) l'appareil ne doit pas produire de brouillage, et (2) l'utilisateur de l'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement.

#### **Concerning EVMs Including Detachable Antennas:**

Under Industry Canada regulations, this radio transmitter may only operate using an antenna of a type and maximum (or lesser) gain approved for the transmitter by Industry Canada. To reduce potential radio interference to other users, the antenna type and its gain should be so chosen that the equivalent isotropically radiated power (e.i.r.p.) is not more than that necessary for successful communication. This radio transmitter has been approved by Industry Canada to operate with the antenna types listed in the user guide with the maximum permissible gain and required antenna impedance for each antenna type indicated. Antenna types not included in this list, having a gain greater than the maximum gain indicated for that type, are strictly prohibited for use with this device.



### Concernant les EVMs avec antennes détachables

Conformément à la réglementation d'Industrie Canada, le présent émetteur radio peut fonctionner avec une antenne d'un type et d'un gain maximal (ou inférieur) approuvé pour l'émetteur par Industrie Canada. Dans le but de réduire les risques de brouillage radioélectrique à l'intention des autres utilisateurs, il faut choisir le type d'antenne et son gain de sorte que la puissance isotrope rayonnée équivalente (p.i.r.e.) ne dépasse pas l'intensité nécessaire à l'établissement d'une communication satisfaisante. Le présent émetteur radio a été approuvé par Industrie Canada pour fonctionner avec les types d'antenne énumérés dans le manuel d'usage et ayant un gain admissible maximal et l'impédance requise pour chaque type d'antenne. Les types d'antenne non inclus dans cette liste, ou dont le gain est supérieur au gain maximal indiqué, sont strictement interdits pour l'exploitation de l'émetteur.

#### 3.3 Japan

3.3.1 *Notice for EVMs delivered in Japan:* Please see [http://www.tij.co.jp/lstds/ti\\_ja/general/eStore/notice\\_01.page](http://www.tij.co.jp/lstds/ti_ja/general/eStore/notice_01.page) 日本国内に輸入される評価用キット、ボードについては、次のところをご覧ください。

<https://www.ti.com/ja-jp/legal/notice-for-evaluation-kits-delivered-in-japan.html>

3.3.2 *Notice for Users of EVMs Considered "Radio Frequency Products" in Japan:* EVMs entering Japan may not be certified by TI as conforming to Technical Regulations of Radio Law of Japan.

If User uses EVMs in Japan, not certified to Technical Regulations of Radio Law of Japan, User is required to follow the instructions set forth by Radio Law of Japan, which includes, but is not limited to, the instructions below with respect to EVMs (which for the avoidance of doubt are stated strictly for convenience and should be verified by User):

1. Use EVMs in a shielded room or any other test facility as defined in the notification #173 issued by Ministry of Internal Affairs and Communications on March 28, 2006, based on Sub-section 1.1 of Article 6 of the Ministry's Rule for Enforcement of Radio Law of Japan,
2. Use EVMs only after User obtains the license of Test Radio Station as provided in Radio Law of Japan with respect to EVMs, or
3. Use of EVMs only after User obtains the Technical Regulations Conformity Certification as provided in Radio Law of Japan with respect to EVMs. Also, do not transfer EVMs, unless User gives the same notice above to the transferee. Please note that if User does not follow the instructions above, User will be subject to penalties of Radio Law of Japan.

【無線電波を送信する製品の開発キットをお使いになる際の注意事項】 開発キットの中には技術基準適合証明を受けていないものがあります。技術適合証明を受けていないものご使用に際しては、電波法遵守のため、以下のいずれかの措置を取っていただく必要がありますのでご注意ください。

1. 電波法施行規則第6条第1項第1号に基づく平成18年3月28日総務省告示第173号で定められた電波暗室等の試験設備でご使用いただく。
2. 実験局の免許を取得後ご使用いただく。
3. 技術基準適合証明を取得後ご使用いただく。

なお、本製品は、上記の「ご使用にあたっての注意」を譲渡先、移転先に通知しない限り、譲渡、移転できないものとします。

上記を遵守頂けない場合は、電波法の罰則が適用される可能性があることをご留意ください。日本テキサス・イ

ンスツルメンツ株式会社

東京都新宿区西新宿 6 丁目 2 4 番 1 号

西新宿三井ビル

3.3.3 *Notice for EVMs for Power Line Communication:* Please see [http://www.tij.co.jp/lstds/ti\\_ja/general/eStore/notice\\_02.page](http://www.tij.co.jp/lstds/ti_ja/general/eStore/notice_02.page)

電力線搬送波通信についての開発キットをお使いになる際の注意事項については、次のところをご覧ください。 <https://www.ti.com/ja-jp/legal/notice-for-evaluation-kits-for-power-line-communication.html>

#### 3.4 European Union

3.4.1 *For EVMs subject to EU Directive 2014/30/EU (Electromagnetic Compatibility Directive):*

This is a class A product intended for use in environments other than domestic environments that are connected to a low-voltage power-supply network that supplies buildings used for domestic purposes. In a domestic environment this product may cause radio interference in which case the user may be required to take adequate measures.

- 
- 4 *EVM Use Restrictions and Warnings:*
    - 4.1 EVMS ARE NOT FOR USE IN FUNCTIONAL SAFETY AND/OR SAFETY CRITICAL EVALUATIONS, INCLUDING BUT NOT LIMITED TO EVALUATIONS OF LIFE SUPPORT APPLICATIONS.
    - 4.2 User must read and apply the user guide and other available documentation provided by TI regarding the EVM prior to handling or using the EVM, including without limitation any warning or restriction notices. The notices contain important safety information related to, for example, temperatures and voltages.
    - 4.3 *Safety-Related Warnings and Restrictions:*
      - 4.3.1 User shall operate the EVM within TI's recommended specifications and environmental considerations stated in the user guide, other available documentation provided by TI, and any other applicable requirements and employ reasonable and customary safeguards. Exceeding the specified performance ratings and specifications (including but not limited to input and output voltage, current, power, and environmental ranges) for the EVM may cause personal injury or death, or property damage. If there are questions concerning performance ratings and specifications, User should contact a TI field representative prior to connecting interface electronics including input power and intended loads. Any loads applied outside of the specified output range may also result in unintended and/or inaccurate operation and/or possible permanent damage to the EVM and/or interface electronics. Please consult the EVM user guide prior to connecting any load to the EVM output. If there is uncertainty as to the load specification, please contact a TI field representative. During normal operation, even with the inputs and outputs kept within the specified allowable ranges, some circuit components may have elevated case temperatures. These components include but are not limited to linear regulators, switching transistors, pass transistors, current sense resistors, and heat sinks, which can be identified using the information in the associated documentation. When working with the EVM, please be aware that the EVM may become very warm.
      - 4.3.2 EVMs are intended solely for use by technically qualified, professional electronics experts who are familiar with the dangers and application risks associated with handling electrical mechanical components, systems, and subsystems. User assumes all responsibility and liability for proper and safe handling and use of the EVM by User or its employees, affiliates, contractors or designees. User assumes all responsibility and liability to ensure that any interfaces (electronic and/or mechanical) between the EVM and any human body are designed with suitable isolation and means to safely limit accessible leakage currents to minimize the risk of electrical shock hazard. User assumes all responsibility and liability for any improper or unsafe handling or use of the EVM by User or its employees, affiliates, contractors or designees.
    - 4.4 User assumes all responsibility and liability to determine whether the EVM is subject to any applicable international, federal, state, or local laws and regulations related to User's handling and use of the EVM and, if applicable, User assumes all responsibility and liability for compliance in all respects with such laws and regulations. User assumes all responsibility and liability for proper disposal and recycling of the EVM consistent with all applicable international, federal, state, and local requirements.
  5. *Accuracy of Information:* To the extent TI provides information on the availability and function of EVMs, TI attempts to be as accurate as possible. However, TI does not warrant the accuracy of EVM descriptions, EVM availability or other information on its websites as accurate, complete, reliable, current, or error-free.
  6. *Disclaimers:*
    - 6.1 EXCEPT AS SET FORTH ABOVE, EVMS AND ANY MATERIALS PROVIDED WITH THE EVM (INCLUDING, BUT NOT LIMITED TO, REFERENCE DESIGNS AND THE DESIGN OF THE EVM ITSELF) ARE PROVIDED "AS IS" AND "WITH ALL FAULTS." TI DISCLAIMS ALL OTHER WARRANTIES, EXPRESS OR IMPLIED, REGARDING SUCH ITEMS, INCLUDING BUT NOT LIMITED TO ANY EPIDEMIC FAILURE WARRANTY OR IMPLIED WARRANTIES OF MERCHANTABILITY OR FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF ANY THIRD PARTY PATENTS, COPYRIGHTS, TRADE SECRETS OR OTHER INTELLECTUAL PROPERTY RIGHTS.
    - 6.2 EXCEPT FOR THE LIMITED RIGHT TO USE THE EVM SET FORTH HEREIN, NOTHING IN THESE TERMS SHALL BE CONSTRUED AS GRANTING OR CONFERRING ANY RIGHTS BY LICENSE, PATENT, OR ANY OTHER INDUSTRIAL OR INTELLECTUAL PROPERTY RIGHT OF TI, ITS SUPPLIERS/LICENSORS OR ANY OTHER THIRD PARTY, TO USE THE EVM IN ANY FINISHED END-USER OR READY-TO-USE FINAL PRODUCT, OR FOR ANY INVENTION, DISCOVERY OR IMPROVEMENT, REGARDLESS OF WHEN MADE, CONCEIVED OR ACQUIRED.
  7. *USER'S INDEMNITY OBLIGATIONS AND REPRESENTATIONS.* USER WILL DEFEND, INDEMNIFY AND HOLD TI, ITS LICENSORS AND THEIR REPRESENTATIVES HARMLESS FROM AND AGAINST ANY AND ALL CLAIMS, DAMAGES, LOSSES, EXPENSES, COSTS AND LIABILITIES (COLLECTIVELY, "CLAIMS") ARISING OUT OF OR IN CONNECTION WITH ANY HANDLING OR USE OF THE EVM THAT IS NOT IN ACCORDANCE WITH THESE TERMS. THIS OBLIGATION SHALL APPLY WHETHER CLAIMS ARISE UNDER STATUTE, REGULATION, OR THE LAW OF TORT, CONTRACT OR ANY OTHER LEGAL THEORY, AND EVEN IF THE EVM FAILS TO PERFORM AS DESCRIBED OR EXPECTED.

8. *Limitations on Damages and Liability:*

8.1 *General Limitations.* IN NO EVENT SHALL TI BE LIABLE FOR ANY SPECIAL, COLLATERAL, INDIRECT, PUNITIVE, INCIDENTAL, CONSEQUENTIAL, OR EXEMPLARY DAMAGES IN CONNECTION WITH OR ARISING OUT OF THESE TERMS OR THE USE OF THE EVMS , REGARDLESS OF WHETHER TI HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES. EXCLUDED DAMAGES INCLUDE, BUT ARE NOT LIMITED TO, COST OF REMOVAL OR REINSTALLATION, ANCILLARY COSTS TO THE PROCUREMENT OF SUBSTITUTE GOODS OR SERVICES, RETESTING, OUTSIDE COMPUTER TIME, LABOR COSTS, LOSS OF GOODWILL, LOSS OF PROFITS, LOSS OF SAVINGS, LOSS OF USE, LOSS OF DATA, OR BUSINESS INTERRUPTION. NO CLAIM, SUIT OR ACTION SHALL BE BROUGHT AGAINST TI MORE THAN TWELVE (12) MONTHS AFTER THE EVENT THAT GAVE RISE TO THE CAUSE OF ACTION HAS OCCURRED.

8.2 *Specific Limitations.* IN NO EVENT SHALL TI'S AGGREGATE LIABILITY FROM ANY USE OF AN EVM PROVIDED HEREUNDER, INCLUDING FROM ANY WARRANTY, INDEMNITY OR OTHER OBLIGATION ARISING OUT OF OR IN CONNECTION WITH THESE TERMS, , EXCEED THE TOTAL AMOUNT PAID TO TI BY USER FOR THE PARTICULAR EVM(S) AT ISSUE DURING THE PRIOR TWELVE (12) MONTHS WITH RESPECT TO WHICH LOSSES OR DAMAGES ARE CLAIMED. THE EXISTENCE OF MORE THAN ONE CLAIM SHALL NOT ENLARGE OR EXTEND THIS LIMIT.

9. *Return Policy.* Except as otherwise provided, TI does not offer any refunds, returns, or exchanges. Furthermore, no return of EVM(s) will be accepted if the package has been opened and no return of the EVM(s) will be accepted if they are damaged or otherwise not in a resalable condition. If User feels it has been incorrectly charged for the EVM(s) it ordered or that delivery violates the applicable order, User should contact TI. All refunds will be made in full within thirty (30) working days from the return of the components(s), excluding any postage or packaging costs.

10. *Governing Law:* These terms and conditions shall be governed by and interpreted in accordance with the laws of the State of Texas, without reference to conflict-of-laws principles. User agrees that non-exclusive jurisdiction for any dispute arising out of or relating to these terms and conditions lies within courts located in the State of Texas and consents to venue in Dallas County, Texas. Notwithstanding the foregoing, any judgment may be enforced in any United States or foreign court, and TI may seek injunctive relief in any United States or foreign court.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265  
Copyright © 2023, Texas Instruments Incorporated

## IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you fully indemnify TI and its representatives against any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to [TI's Terms of Sale](#), [TI's General Quality Guidelines](#), or other applicable terms available either on [ti.com](http://ti.com) or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products. Unless TI explicitly designates a product as custom or customer-specified, TI products are standard, catalog, general purpose devices.

TI objects to and rejects any additional or different terms you may propose.

Copyright © 2026, Texas Instruments Incorporated

Last updated 10/2025